MITSUBISHI MICROCOMPUTERS **7531 Group**

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

DESCRIPTION

The 7531 Group is the 8-bit microcomputer based on the 740 family core technology.

The 7531 Group has a serial I/O, 8-bit timers, and an A-D converter, and is useful for control of home electric appliances and office automation equipment.

FFATURES

permitting CR oscillation)
Watchdog timer
Power source voltage
At 8 MHz XIN oscillation frequency at ceramic oscillation
4.0 to 5.5 V
At 4 MHz XIN oscillation frequency at ceramic oscillation
At 2 MHz XIN oscillation frequency at ceramic oscillation
At 4 MHz XIN oscillation frequency at CR oscillation
At 2 MHz XIN oscillation frequency at CR oscillation
2.4 to 5.5 V
At 1 MHz XIN oscillation frequency at CR oscillation
2.2 to 5.5 V
Power dissipation
Operating temperature range
(-40 to 85 °C or -40 to 125 °C for extended operating temperature
version (Note)) Note: The total time is limited as follows:
6000 hours at 55 to 85 °C, 1000 hours at 85 to 125 °C
APPLICATION

Office automation equipment, factory automation equipment, home electric appliances, consumer electronics, car, etc.

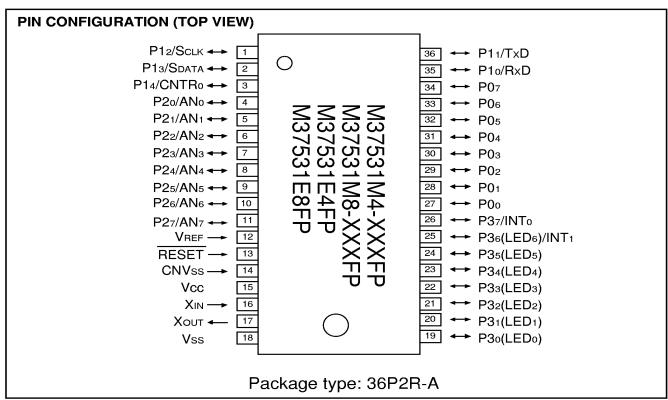


Fig. 1 Pin configuration (36P2R package type)



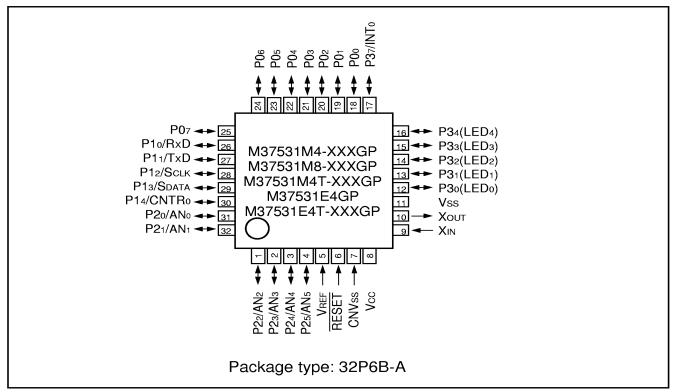


Fig. 2 Pin configuration (32P6B package type)

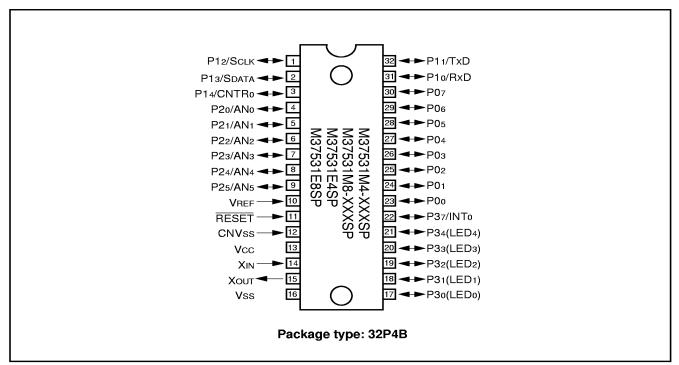


Fig. 3 Pin configuration (32P4B package type)



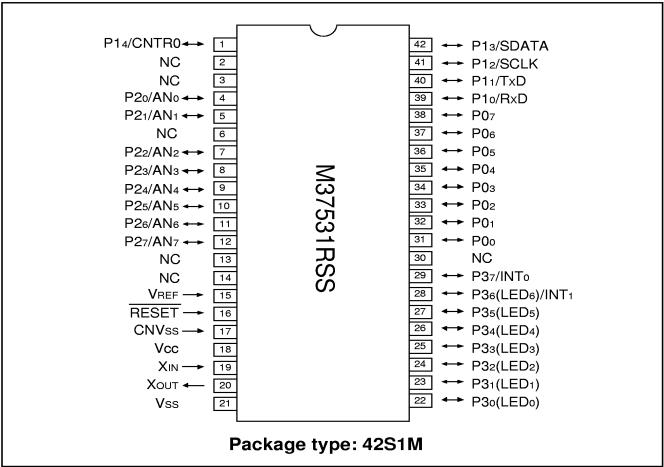


Fig. 4 Pin configuration (42S1M package type)



FUNCTIONAL BLOCK

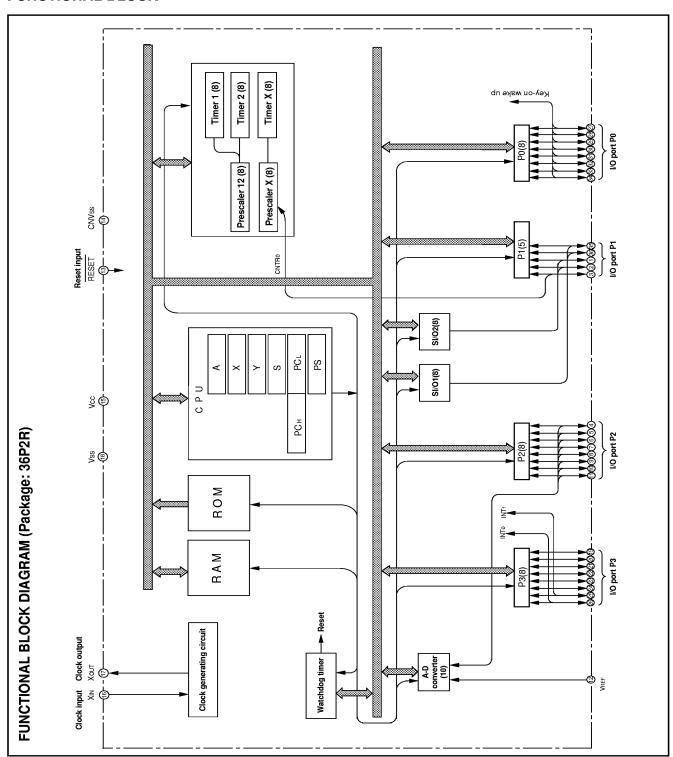


Fig. 5 Functional block diagram (36P2R package)



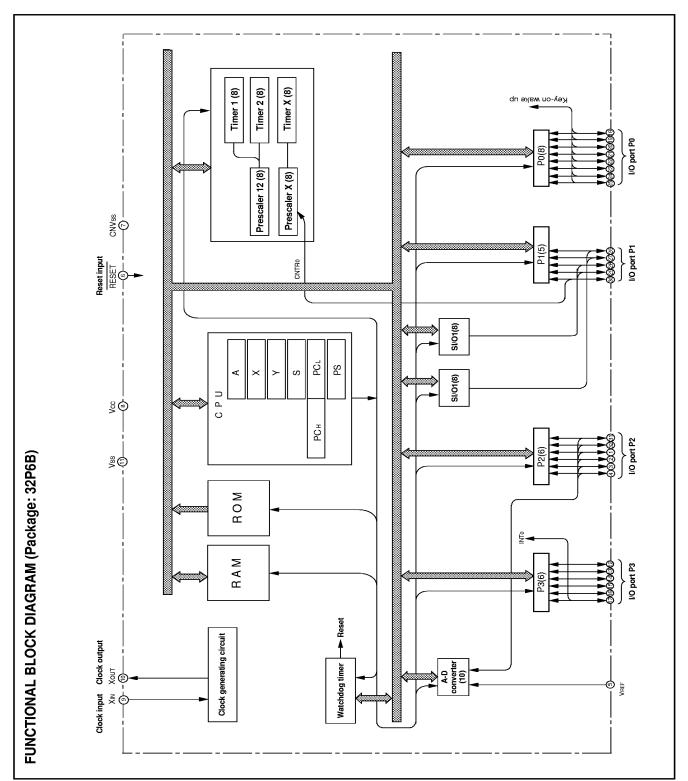


Fig. 6 Functional block diagram (32P6B package)



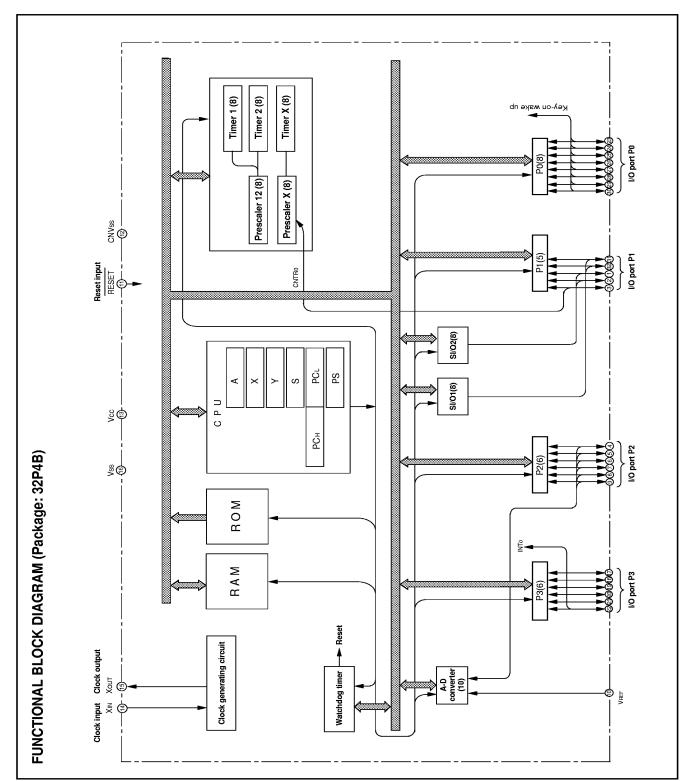


Fig. 7 Functional block diagram (32P4B package)



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SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

PIN DESCRIPTION

Table 1 Pin description

Pin	Name	Function	Function expect a port function					
Vcc, Vss	Power source	•Apply voltage of 2.2–5.5 V to Vcc, and 0 V to Vss.	· · ·					
VREF	Analog reference voltage	•Reference voltage input pin for A-D converter						
CNVss	CNVss	Chip operating mode control pin, which is always connected to Vss.						
RESET	Reset input	Reset input pin for active "L"						
XIN	Clock input	•Input and output pins for main clock generating circuit	•Input and output pins for main clock generating circuit					
		•Connect a ceramic resonator or quartz crystal oscillator between	n the Xin and Xo∪⊤ pins.					
Хоит	Clock output	•For using CR oscillator, short between the X _{IN} and X _{OUT} pins, ar	nd connect the capacitor and resistor.					
		•If an external clock is used, connect the clock source to the XIN p	oin and leave the Xo∪⊤ pin open.					
P00-P07	I/O port P0	•8-bit I/O port.	•Key-input (key-on wake up					
		I/O direction register allows each pin to be individually programmed as either input or output.	interrupt input) pins					
		•CMOS compatible input level						
		•CMOS 3-state output structure						
		Whether a built-in pull-up resistor is to be used or not can be determined by program.						
P1o/RxD	I/O port P1	•5-bit I/O port	•Serial I/O1 function pin					
P1 ₁ /TxD		•I/O direction register allows each pin to be individually pro-						
P12/SCLK		grammed as either input or output.	•Serial I/O2 function pin					
P13/SDATA		•CMOS compatible input level						
P14/CNTRo		•CMOS 3-state output structure	•Timer X function pin					
		•CMOS/TTL level can be switched for P1o, P12 and P13						
P2o/ANo- P27/AN7	I/O port P2	•8-bit I/O port having almost the same function as P0	•Input pins for A-D converter					
F2//AIN/		•CMOS compatible input level						
		•CMOS 3-state output structure						
P30-P35	I/O port P3	•8-bit I/O port						
		•I/O direction register allows each pin to be individually programmed as either input or output						
		•CMOS compatible input level (CMOS/TTL level can be switched	for P36 and P37).					
		•CMOS 3-state output structure						
		•P3o to P3e can output a large current for driving LED.						
P36/INT1 P37/INT0		Whether a built-in pull-up resistor is to be used or not can be determined by program.	•Interrupt input pins					



GROUP EXPANSION

Mitsubishi plans to expand the 7531 group as follow:

Memory type

Support for Mask ROM version, One Time PROM version, and Emulator MCU .

Memory size

Package

32P4B	32 pin shrink plastic molded DIP
32P6B-A	0.8 mm-pitch plastic molded QFP
36P2R-A	0.8 mm-pitch plastic molded SOP
42S1M 4	2 pin shrink ceramic PIGGY BACK

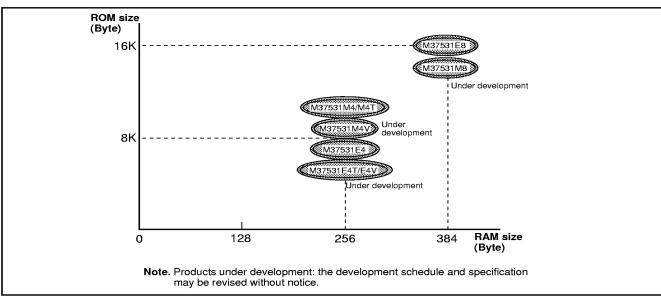


Fig. 8 Memory expansion plan

Currently supported products are listed below.

Table 2 List of supported products

Product	(P) ROM size (bytes) ROM size for User ()	RAM size (bytes)	Package	Remarks
M37531M4-XXXSP			32P4B	Mask ROM version
M37531E4SP			32546	One Time PROM version (blank)
M37531M4-XXXFP			36P2R-A	Mask ROM version
M37531E4FP			36FZN-A	One Time PROM version (blank)
M37531M4-XXXGP	9102 (9062)			Mask ROM version
M37531M4T-XXXGP		256		Mask ROM version (extended operating temperature version)
M37531M4V-XXXGP	8192 (8062)	230		Mask ROM version (extended operating temperature 125 °C version)
M37531E4GP			32P6B-A	One Time PROM version (blank)
M37531E4T-XXXGP				One Time PROM version (shipped after writing, extended operating
				temperature version)
M37531E4V-XXXGP]			One Time PROM version (shipped after writing, extended operating
				temperature 125 °C version)
M37531M8-XXXSP			32P4B	Mask ROM version
M37531E8SP]			One Time PROM version (blank)
M37531M8-XXXFP	16384 (16254)	384		Mask ROM version
M37531E8FP	1	384	36P2R-A	One Time PROM version (blank)
M37531M8-XXXGP	1		32P6B-A	Mask ROM version
M37531RSS		42S1M		Emulator MCU



FUNCTIONAL DESCRIPTION

Central Processing Unit (CPU)

The 7531 Group uses the standard 740 family instruction set. Refer to the table of 740 family addressing modes and machine-language instructions or the 740 Family Software MANUAL for details on each instruction set.

Machine-resident 740 family instructions are as follows:

- 1. The FST and SLW instructions cannot be used.
- 2. The MUL and DIV instructions cannot be used.
- 3. The WIT instruction can be used.
- 4. The STP instruction can be used.

[CPU Mode Register] CPUM

The CPU mode register contains the stack page selection bit. This register is allocated at address 003B₁₆.

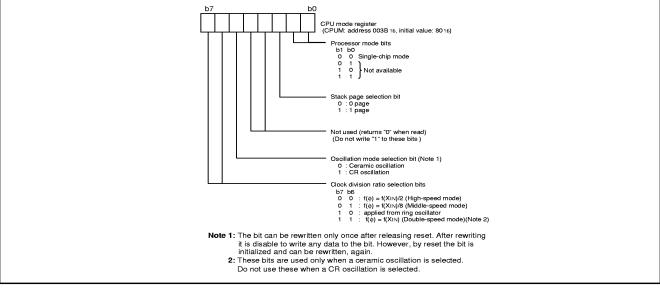


Fig. 9 Structure of CPU mode register

Switching method of CPU mode register

Switch the CPU mode register (CPUM) at the head of program after releasing Reset in the following method.

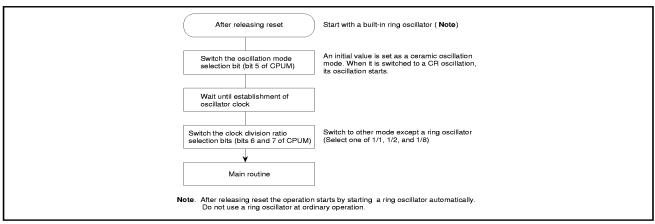


Fig. 10 Switching method of CPU mode register



Memory

Special function register (SFR) area

The SFR area in the zero page contains control registers such as I/O ports and timers.

RAM

RAM is used for data storage and for a stack area of subroutine calls and interrupts.

ROM

The first 128 bytes and the last 2 bytes of ROM are reserved for device testing and the rest is a user area for storing programs.

Interrupt vector area

The interrupt vector area contains reset and interrupt vectors.

Zero page

The 256 bytes from addresses 000016 to 00FF16 are called the zero page area. The internal RAM and the special function registers (SFR) are allocated to this area.

The zero page addressing mode can be used to specify memory and register addresses in the zero page area. Access to this area with only 2 bytes is possible in the zero page addressing mode.

Special page

The 256 bytes from addresses FF0016 to FFFF16 are called the special page area. The special page addressing mode can be used to specify memory addresses in the special page area. Access to this area with only 2 bytes is possible in the special page addressing mode.

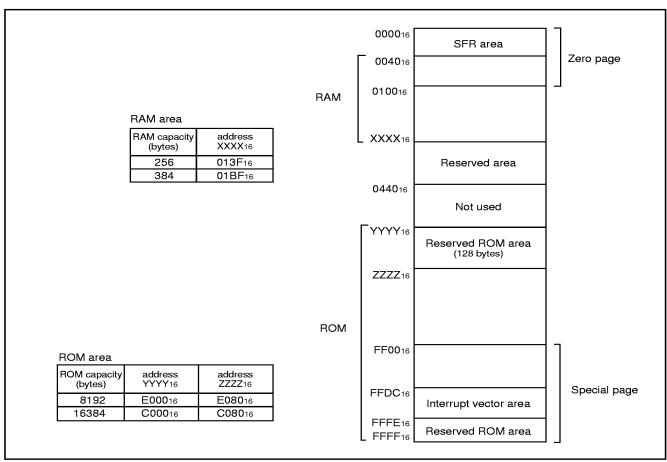


Fig. 11 Memory map diagram



000016	Port P0 (P0)	002016	
000116	Port P0 direction register (P0D)	002116	
000216	Port P1 (P1)	002216	
000316	Port P1 direction register (P1D)	002316	
000416	Port P2 (P2)	002416	
000516	Port P2 direction register (P2D)	002516	
000616	Port P3 (P3)	002616	
000716	Port P3 direction register (P3D)	002716	
000816		002816	Prescaler 12 (PRE12)
000916		002916	Timer 1 (T1)
000A16		002A ₁₆	Timer 2 (T2)
000B16		002B ₁₆	Timer X mode register (TM)
000C16		002C16	Prescaler X (PREX)
000D16		002D16	Timer X (TX)
000E16		002E16	Timer count source set register (TCSS)
000F16		002F16	
001016		003016	Serial I/O2 control register (SIO2CON)
001116		003116	Serial I/O2 register (SIO2)
001216		003216	
001316		003316	
001416		003416	A-D control register (ADCON)
001516		003516	A-D conversion register (low-order) (ADL)
001616	Pull-up control register (PULL)	003616	A-D conversion register (high-order) (ADH)
001716	Port P1P3 control register (P1P3C)	003716	
001816	Transmit/Receive buffer register (TB/RB)	003816	MISRG
001916	Serial I/O1 status register (SIO1STS)	003916	Watchdog timer control register (WDTCON)
01A16	Serial I/O1 control register (SIO1CON)	003A ₁₆	Interrupt edge selection register (INTEDGE)
001B16	UART control register (UARTCON)	003B ₁₆	CPU mode register (CPUM)
001C16	Baud rate generator (BRG)	003C ₁₆	Interrupt request register 1 (IREQ1)
001 D16		003D16	
001E16		003E16	Interrupt control register 1 (ICON1)
001F16		003F16	

Fig. 12 Memory map of special function register (SFR)



I/O Ports

[Direction registers] PiD

The I/O ports have direction registers which determine the input/output direction of each pin. Each bit in a direction register corresponds to one pin, and each pin can be set to be input or output.

When "1" is set to the bit corresponding to a pin, this pin becomes an output port. When "0" is set to the bit, the pin becomes an input port. When data is read from a pin set to output, not the value of the pin itself but the value of port latch is read. Pins set to input are floating, and permit reading pin values.

If a pin set to input is written to, only the port latch is written to and the pin remains floating.

[Pull-up control] PULL

By setting the pull-up control register (address 001616), ports P0 and P3 can exert pull-up control by program. However, pins set to output are disconnected from this control and cannot exert pull-up control.

[Port P1P3 control] P1P3C

By setting the port P1P3 control register (address 001716), a CMOS input level or a TTL input level can be selected for ports P10, P12, P13, P36, and P37 by program.

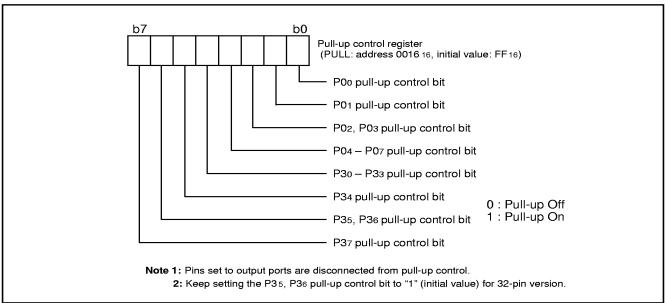


Fig. 13 Structure of pull-up control register

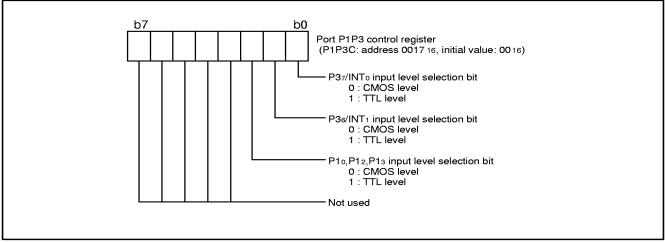


Fig. 14 Structure of port P1P3 control register



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Table 3 I/O port function table

Pin	Name	Input/output	I/O format	Non-port function	Related SFRs	Diagram No.
P00-P07	I/O port P0	I/O individual bits	CMOS compatible input level CMOS 3-state output	Key input interrupt	Pull-up control register	(1)
P1o/RxD	I/O port P1		(Note)	Serial I/O1 function	Serial I/O1 control	(2)
P11/TxD				input/output	register	(3)
P12/Sclk				Serial I/O2 function	Serial I/O2 control	(4)
P13/SDATA				input/output	register	(5)
P14/CNTRo				Timer X function input/output	Timer X mode register	(6)
P2o/ANo- P27/AN7	I/O port P2			A-D conversion input	A-D control register	(7)
P30-P35	I/O port P3					(8)
P36/INT1				External interrupt	Interrupt edge	(9)
P37/INTo				input	selection register	(9)

Note: Ports P10, P12, P13, P36, and P37 are CMOS/TTL level.



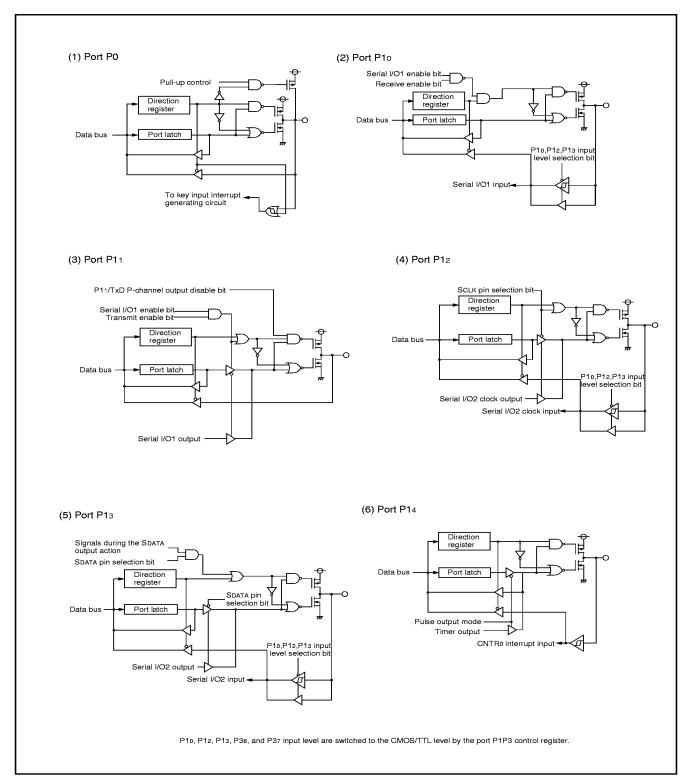


Fig. 15 Block diagram of ports (1)



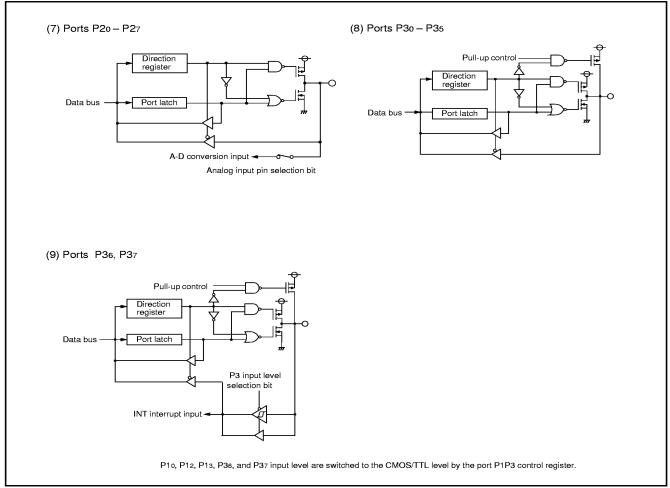


Fig. 16 Block diagram of ports (2)



Interrupts

Interrupts occur by 12 different sources: 4 external sources, 7 internal sources and 1 software source.

Interrupt control

All interrupts except the BRK instruction interrupt have an interrupt request bit and an interrupt enable bit, and they are controlled by the interrupt disable flag. When the interrupt enable bit and the interrupt request bit are set to "1" and the interrupt disable flag is set to "0", an interrupt is accepted.

The interrupt request bit can be cleared by program but not be set. The interrupt enable bit can be set and cleared by program.

It becomes usable by switching CNTRo and AD conversion interrupt sources with bit 7 of the interrupt edge selection register, timer 2 and serial I/O2 interrupt sources with bit 6, timer X and key-on wake-up interrupt sources with bit 5, and serial I/O1 transmit and INT1 interrupt sources with bit 4.

The reset and BRK instruction interrupt can never be disabled with any flag or bit. All interrupts except these are disabled when the interrupt disable flag is set.

When several interrupts occur at the same time, the interrupts are received according to priority.

Interrupt operation

Upon acceptance of an interrupt the following operations are automatically performed:

- 1. The processing being executed is stopped.
- 2. The contents of the program counter and processor status register are automatically pushed onto the stack.
- The interrupt disable flag is set and the corresponding interrupt request bit is cleared.
- 4. Concurrently with the push operation, the interrupt destination address is read from the vector table into the program counter.

Notes on use

When the active edge of an external interrupt (INTo, INT1,CNTRo) is set, the interrupt request bit may be set.

Therefore, please take following sequence:

- 1. Disable the external interrupt which is selected.
- 2. Change the active edge in interrupt edge selection register. (in case of CNTRo: Timer X mode register)
- 3. Clear the set interrupt request bit to "0".
- 4. Enable the external interrupt which is selected.

Table 4 Interrupt vector address and priority

	B	ty Vector addresses (Note 1) High-order Low-order		1	Remarks	
Interrupt source	Priority			Interrupt request generating conditions		
Reset (Note 2)	1	FFFD ₁₆	FFFC16	At reset input	Non-maskable	
Serial I/O1 receive	2	FFFB16	FFFA ₁₆	At completion of serial I/O1 data receive	Valid when serial I/O1 is selected	
Serial I/O1 transmit	3	FFF9 ₁₆	FFF816	At completion of serial I/O1 transmit shift or when transmit buffer is empty	Valid when serial I/O1 is selected	
INT1 (Note 3)				At detection of either rising or falling edge of INT1 input	External interrupt (active edge selectable)	
INTo	4	FFF716	FFF616	At detection of either rising or falling edge of INTo input	External interrupt (active edge selectable)	
Timer X	5	FFF516	FFF416	At timer X underflow		
Key-on wake-up				At falling of conjunction of input logical level for port P0 (at input)	External interrupt (valid at falling)	
Timer 1	6	FFF316	FFF216	At timer 1 underflow	STP release timer underflow	
Timer 2	7	FFF116	FFF016	At timer 2 underflow		
Serial I/O2	1			At completion of transmit/receive shift		
CNTR ₀	8	FFEF16	FFEE16	At detection of either rising or falling edge of CNTRo input	External interrupt (active edge selectable)	
A-D conversion				At completion of A-D conversion	T	
BRK instruction	9	FFED16	FFEC ₁₆	At BRK instruction execution	Non-maskable software interrupt	

Note 1: Vector addressed contain internal jump destination addresses.

- 2: Reset function in the same way as an interrupt with the highest priority.
- 3: It is an interrupt which can use only for 32 pin version.



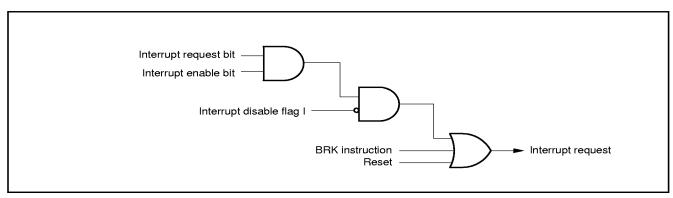


Fig. 17 Interrupt control

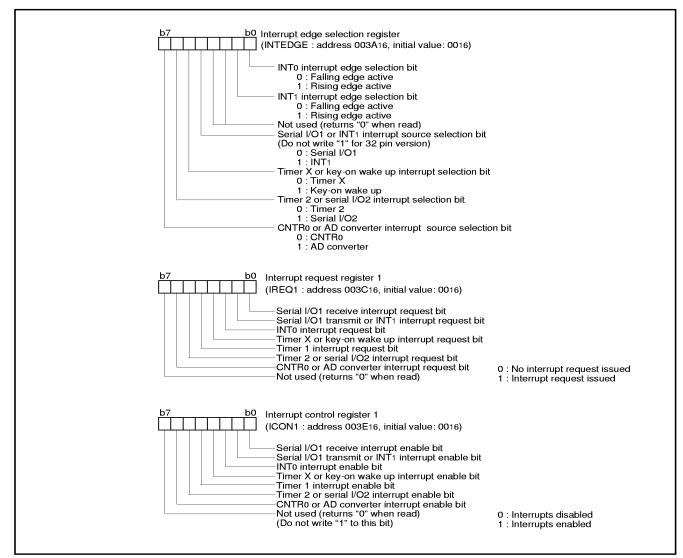


Fig. 18 Structure of Interrupt-related registers



Key Input Interrupt (Key-On Wake-Up)

A key-on wake-up interrupt request is generated by applying "L" level to any pin of port P0 that has been set to input mode. In other words, it is generated when the AND of input level goes from "1" to "0". An example of using a key input interrupt is shown in Figure 19, where an interrupt request is generated by pressing one of the keys provided as an active-low key matrix which uses ports P00 to P04 as input ports.

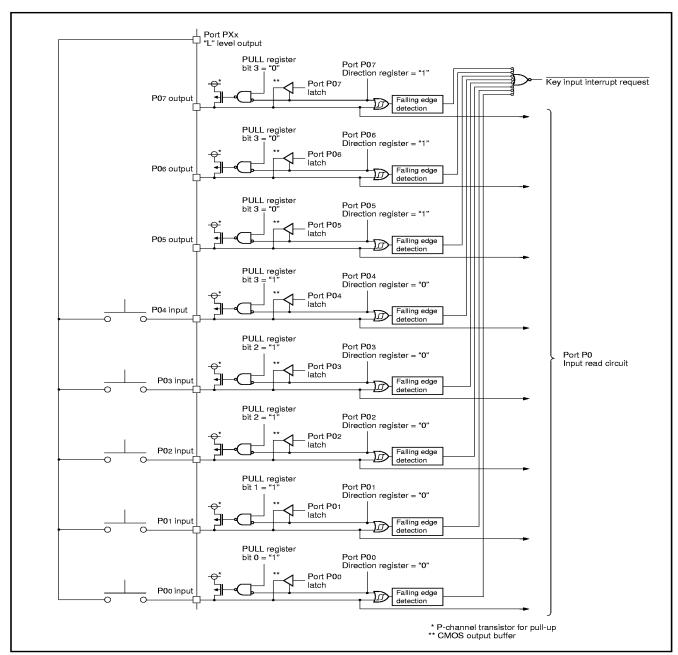


Fig. 19 Connection example when using key input interrupt and port P0 block diagram



Timers

The 7531 Group has 3 timers: timer X, timer 1 and timer 2.

The division ratio of every timer and prescaler is 1/(n+1) provided that the value of the timer latch or prescaler is n.

All the timers are down count timers. When a timer reaches "0", an underflow occurs at the next count pulse, and the corresponding timer latch is reloaded into the timer. When a timer underflows, the interrupt request bit corresponding to each timer is set to "1".

●Timer 1, Timer 2

Prescaler 12 always counts $f(X_{IN})/16$. Timer 1 and timer 2 always count the prescaler output and periodically sets the interrupt request bit

Timer X

Timer X can be selected in one of 4 operating modes by setting the timer X mode register.

Timer Mode

The timer counts the signal selected by the timer X count source selection bit.

Pulse Output Mode

The timer counts the signal selected by the timer X count source selection bit, and outputs a signal whose polarity is inverted each time the timer value reaches "0", from the CNTRo pin.

When the CNTRo active edge switch bit is "0", the output of the CNTRo pin is started with an "H" output.

At "1", this output is started with an "L" output. When using a timer in this mode, set the port P14 direction register to output mode.

• Event Counter Mode

The operation in the event counter mode is the same as that in the timer mode except that the timer counts the input signal from the CNTRo pin.

When the CNTRo active edge switch bit is "0", the timer counts the rising edge of the CNTRo pin. When this bit is "1", the timer counts the falling edge of the CNTRo pin.

• Pulse Width Measurement Mode

When the CNTRo active edge switch bit is "0", the timer counts the signal selected by the timer X count source selection bit while the CNTRo pin is "H". When this bit is "1", the timer counts the signal while the CNTRo pin is "L".

In any mode, the timer count can be stopped by setting the timer X count stop bit to "1". Each time the timer overflows, the interrupt request bit is set.

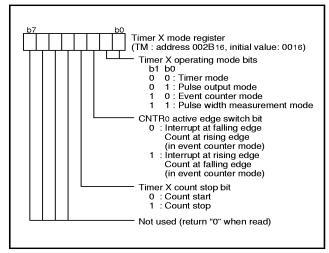


Fig. 20 Structure of timer X mode register

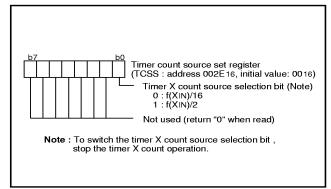


Fig. 21 Timer count source setting register



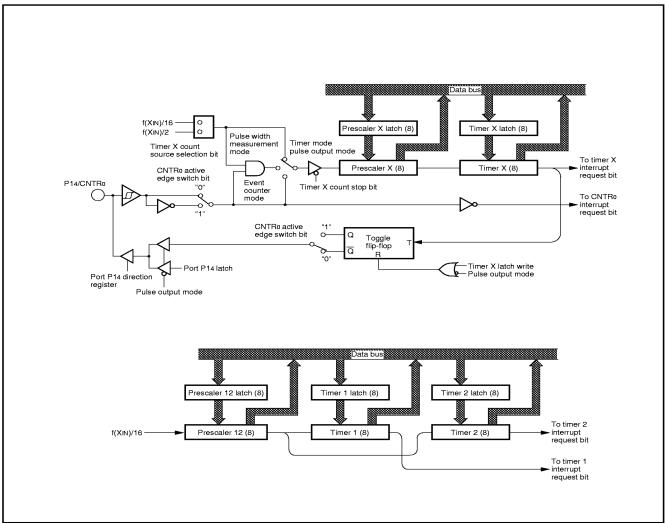


Fig. 22 Block diagram of timer X, timer 1 and timer 2



Serial I/O

●Serial I/O1

Serial I/O1 can be used as an asynchronous (UART) serial I/O. A dedicated timer (baud rate generator) is also provided for baud rate generation when serial I/O1 is in operation.

Eight serial data transfer formats can be selected, and the transfer formats to be used by a transmitter and a receiver must be identical. Each of the transmit and receive shift registers has a buffer register (the same address on memory). Since the shift register cannot be written to or read from directly, transmit data is written to the transmit

buffer, and receive data is read from the respective buffer registers. These buffer registers can also hold the next data to be transmitted and receive 2-byte receive data in succession.

By selecting "1" for continuous transmit valid bit (bit 2 of SIO1CON), continuous transmission of the same data is made possible.

This can be used as a simplified PWM.

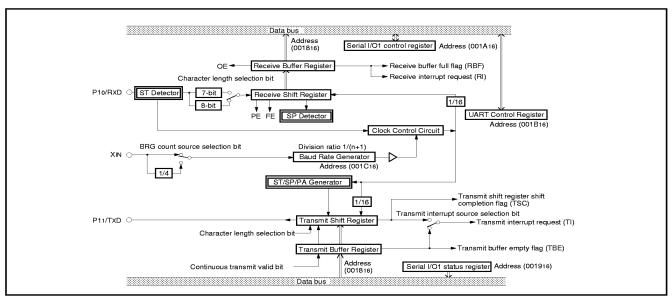


Fig. 23 Block diagram of UART serial I/O

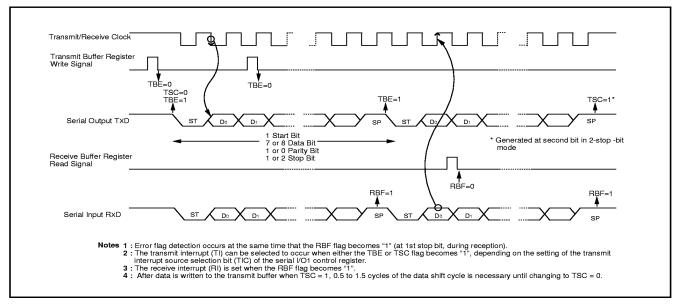


Fig. 24 Operation of UART serial I/O function



[Serial I/O1 control register] SIO1CON

The serial I/O1 control register consists of eight control bits for the serial I/O1 function.

[UART control register] UARTCON

The UART control register consists of four control bits (bits 0 to 3) which are valid when asynchronous serial I/O is selected and set the data format of an data transfer. One bit in this register (bit 4) is always valid and sets the output structure of the P11/TxD pin.

[Serial I/O1 status register] SIO1STS

The read-only serial I/O1 status register consists of seven flags (bits 0 to 6) which indicate the operating status of the serial I/O function and various errors.

The receive buffer full flag (bit 1) is cleared to "0" when the receive buffer is read.

If there is an error, it is detected at the same time that data is transferred from the receive shift register to the receive buffer, and the receive buffer full flag is set. A write to the serial I/O1 status register clears all the error flags OE, PE, FE, and SE (bit 3 to bit 6, respectively). Writing "11" to bits 7 and 6 of the serial I/O1 control register initializes this register.

All bits of the serial I/O1 status register are initialized to "8116" at

[Transmit/Receive buffer register] TB/RB

The transmit buffer and the receive buffer are located at the same address. The transmit buffer is write-only and the receive buffer is read-only. If a character bit length is 7-bit, the MSB of data stored in the receive buffer is "0".

[Baud Rate Generator] BRG

The baud rate generator determines the baud rate for serial transfer. The baud rate generator divides the frequency of the count source by 1/(n + 1), where n is the value written to the baud rate generator.

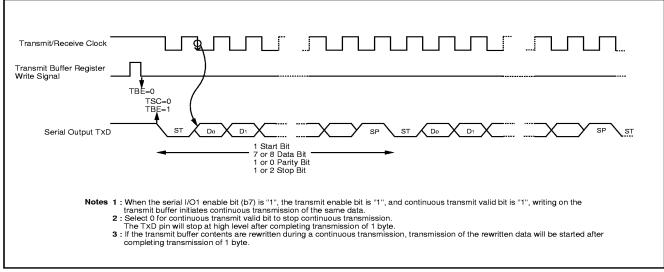


Fig. 25 Continuous transmission operation of UART serial I/O



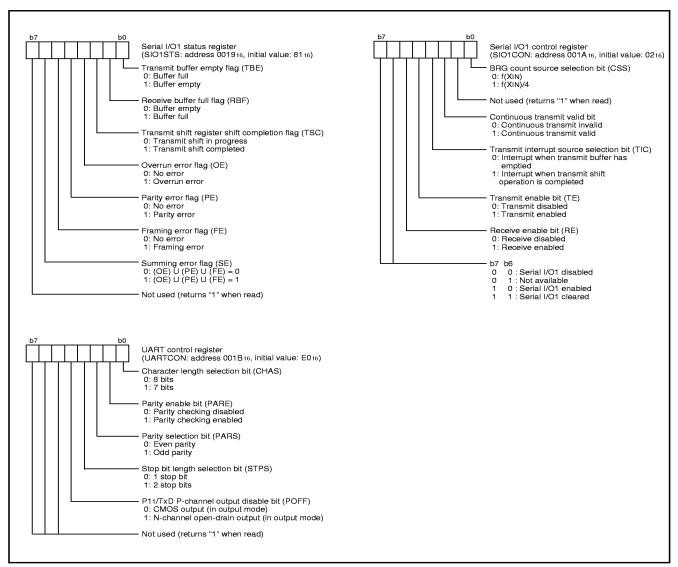


Fig. 26 Structure of serial I/O1-related registers (1)



●Serial I/O2

The serial I/O2 function can be used only for clock synchronous serial I/O.

For clock synchronous serial I/O2 the transmitter and the receiver must use the same clock. When the internal clock is used, transfer is started by a write signal to the serial I/O2 register.

[Serial I/O2 control register] SIO2CON

The serial I/O2 control register contains 8 bits which control various serial I/O functions.

- •Set "0" to bit 3 to receive.
- •At reception, clear bit 7 to "0" by writing a dummy data to the serial I/ O2 register after completion of shift.
- •Bit 7 is set to "1" a half cycle (of the shift clock) earlier than completion of shift operation. Accordingly, when using this bit to confirm shift completion, a half cycle or more of the shift clock must pass after confirming that this bit is set to "1", before performing read/write to the serial I/O2 register.

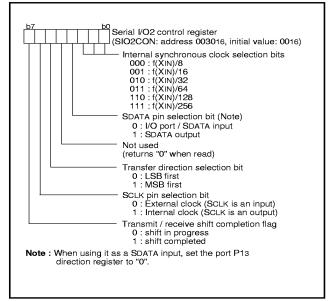


Fig. 27 Structure of serial I/O2 control registers

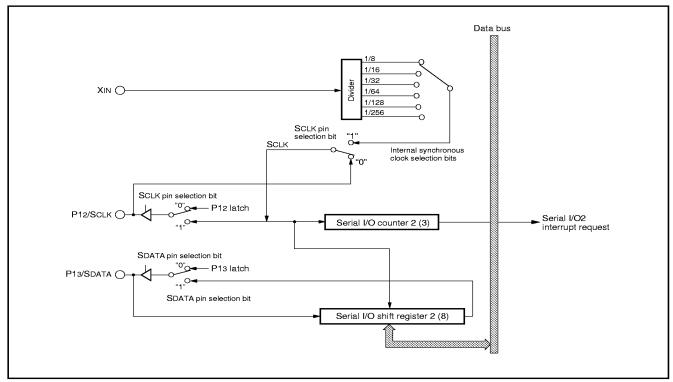


Fig. 28 Block diagram of serial I/O2



Serial I/O2 operation

By writing to the serial I/O2 register (address 003116) the serial I/O2 counter is set to "7".

After writing, the SDATA pin outputs data every time the transfer clock shifts from a high to a low level. And, as the transfer clock shifts from a low to a high, the SDATA pin reads data, and at the same time the contents of the serial I/O2 register are shifted by 1 bit.

When the internal clock is selected as the transfer clock source, the following operations execute as the transfer clock counts up to 8.

- · Serial I/O2 counter is cleared to "0".
- Transfer clock stops at an "H" level.
- Interrupt request bit is set.
- · Shift completion flag is set.

Also, the SDATA pin is in a high impedance state after the data transfer is complete.

When the external clock is selected as the transfer clock source, the interrupt request bit is set as the transfer clock counts up to 8, but external control of the clock is required since it does not stop. Notice that the SDATA pin is not in a high impedance state on the completion of data transfer.

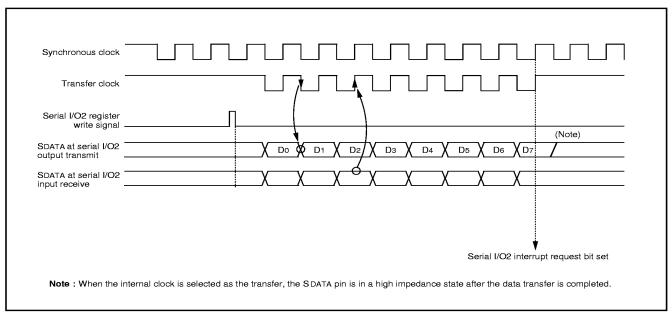


Fig. 29 Serial I/O2 timing (LSB first)



A-D Converter

The functional blocks of the A-D converter are described below.

[A-D conversion register] AD

The A-D conversion register is a read-only register that stores the result of A-D conversion. Do not read out this register during an A-D conversion.

[A-D control register] ADCON

The A-D control register controls the A-D converter. Bit 2 to 0 are analog input pin selection bits. Bit 4 is the AD conversion completion bit. The value of this bit remains at "0" during A-D conversion, and changes to "1" at completion of A-D conversion.

A-D conversion is started by setting this bit to "0".

[Comparison voltage generator]

The comparison voltage generator divides the voltage between AVSS and VREF by 1024, and outputs the divided voltages.

[Channel Selector]

The channel selector selects one of ports P27/AN7 to P20/AN0, and inputs the voltage to the comparator.

[Comparator and control circuit]

The comparator and control circuit compares an analog input voltage with the comparison voltage and stores its result into the A-D conversion register. When A-D conversion is completed, the control circuit sets the AD conversion completion bit and the AD interrupt request bit to "1". Because the comparator is constructed linked to a capacitor, set f(XIN) to 500 kHz or more during A-D conversion.

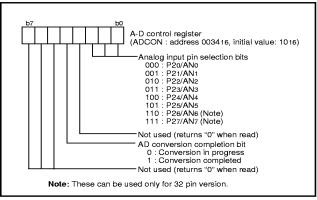


Fig. 30 Structure of A-D control register

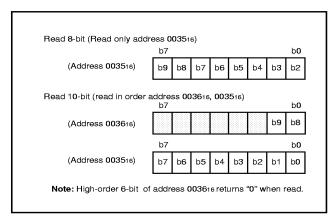


Fig. 31 Structure of A-D conversion register

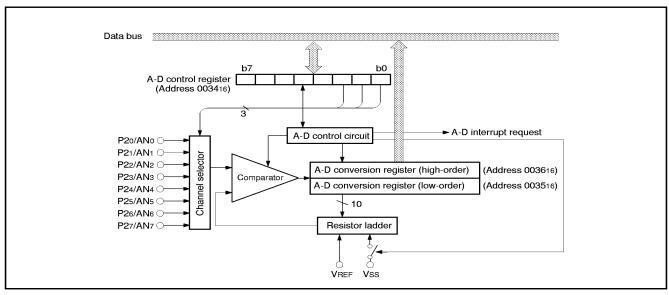


Fig. 32 Block diagram of A-D converter



Watchdog Timer

The watchdog timer gives a means for returning to a reset status when the program fails to run on its normal loop due to a runaway. The watchdog timer consists of an 8-bit watchdog timer H and an 8-bit watchdog timer L, being a 16-bit counter.

Standard operation of watchdog timer

The watchdog timer stops when the watchdog timer control register (address 003916) is not set after reset. Writing an optional value to the watchdog timer control register (address 003916) causes the watchdog timer to start to count down. When the watchdog timer H underflows, an internal reset occurs. Accordingly, it is programmed that the watchdog timer control register (address 003916) can be set before an underflow occurs.

When the watchdog timer control register (address 003916) is read, the values of the high-order 6-bit of the watchdog timer H, STP instruction disable bit and watchdog timer H count source selection bit are read.

Initial value of watchdog timer

By a reset or writing to the watchdog timer control register (address 003916), the watchdog timer H is set to "FF16" and the watchdog timer L is set to "FF16"

Operation of watchdog timer H count source selection bit

A watchdog timer H count source can be selected by bit 7 of the watchdog timer control register (address 003916). When this bit is "0", the count source becomes a watchdog timer L underflow signal. The detection time is 131.072 ms at f(X|N)=8 MHz.

When this bit is "1", the count source becomes $f(X_{IN})/16$. In this case, the detection time is 512 μs at $f(X_{IN})=8$ MHz.

This bit is cleared to "0" after reset.

Operation of STP instruction disable bit

When the watchdog timer is in operation, the STP instruction can be disabled by bit 6 of the watchdog timer control register (address 0039₁₆).

When this bit is "0", the STP instruction is enabled.

When this bit is "1", the STP instruction is disabled, and an internal reset occurs if the STP instruction is executed.

Once this bit is set to "1", it cannot be changed to "0" by program. This bit is cleared to "0" after reset.

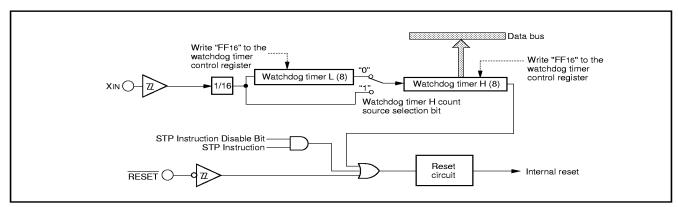


Fig. 33 Block diagram of watchdog timer

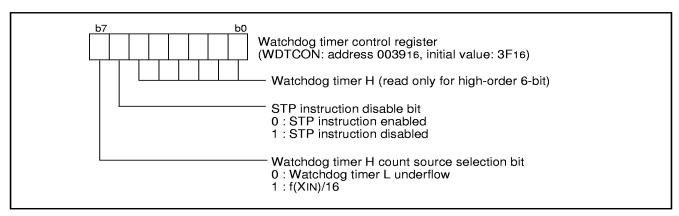


Fig. 34 Structure of watchdog timer control register



Reset Circuit

The microcomputer is put into a reset status by holding the RESET pin at the "L" level for 2 μ s or more when the power source voltage is 2.2 to 5.5 V and XIN is in stable oscillation.

After that, this reset status is released by returning the RESET pin to the "H" level. The program starts from the address having the contents of address FFFD16 as high-order address and the contents of address FFFC16 as low-order address.

In the case of $f(\phi) \le 4$ MHz, the reset input voltage must be 0.8 V or less when the power source voltage passes 4.0 V.

In the case of $f(\phi) \le 2$ MHz, the reset input voltage must be 0.48 V or less when the power source voltage passes 2.4 V.

In the case of f(ϕ) \leq 1 MHz, the reset input voltage must be 0.44 V or less when the power source voltage passes 2.2 V.

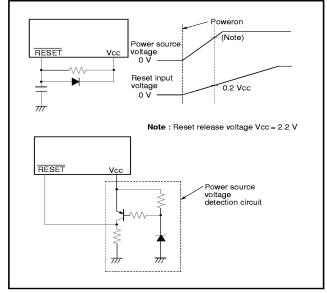


Fig. 35 Example of reset circuit

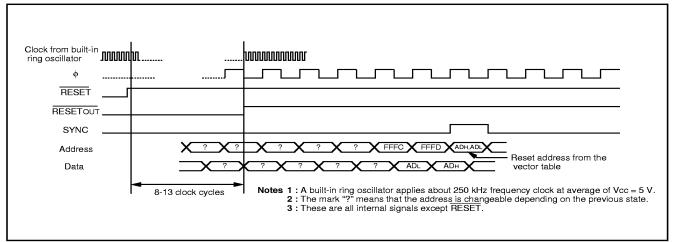


Fig. 36 Timing diagram at reset



	Address Register contents
(1) Port P0 direction register	000116 0016
(2) Port P1 direction register	000316 X X X 0 0 0 0 0
(3) Port P2 direction register	000516 0016
(4) Port P3 direction register	000716 0016
(5) Pull-up control register	001616 FF ₁₆
(6) Port P1P3 control register	001716 0016
(7) Serial I/O1 status register	001916 1 0 0 0 0 0 0 1
(8) Serial I/O1 control register	001A16 0216
(9) UART control register	001B16 1 1 1 0 0 0 0 0
(10) Prescaler 12	002816 FF16
(11) Timer 1	002916 0116
(12) Timer 2	002 A 16 0016
(13) Timer X mode register	002B16 0016
(14) Prescaler X	002C16 FF16
(15) Timer X	002D16 FF16
(16) Timer count source set register	002E16 0016
(17) Serial I/O2 control register	003016 0016
(18) A-D control register	003416 1016
(19) MISRG	003816 0016
(20) Watchdog timer control register	003916 0 0 1 1 1 1 1 1 1
(21) Interrupt edge selection register	003A16 0016
(22) CPU mode register	003B16 1 0 0 0 0 0 0 0
(23) Interrupt request register 1	003C16 0016
(24) Interrupt control register 1	003E16 0016
(25) Processor status register	(PS) X X X X X 1 X X
(26) Program counter	(PCH) Contents of address FFFD16
	(PCL) Contents of address FFFC16

Fig. 37 Internal status of microcomputer at reset



Clock Generating Circuit

An oscillation circuit can be formed by connecting a resonator between X_{IN} and X_{OUT} , and a CR oscillation circuit can be formed by connecting a resistor and a capacitor.

Use the circuit constants in accordance with the resonator manufacturer's recommended values. No external resistor is needed between XIN and XOUT since a feed-back resistor exists on-chip. Set the constants of the resistor and capacitor when a CR oscillator is used, so that a frequency variation due to LSI variation and resistor and capacitor variations may not exceed the standard input frequency.

Oscillation control

Stop mode

When the STP instruction is executed, the internal clock f stops at an "H" level and the XIN oscillator stops. At this time, timer 1 is set to "0116" and prescaler 12 is set to "FF16" when the oscillation stabilization time set bit after release of the STP instruction is "0". On the other hand, timer 1 and prescaler 12 are not set when the above bit is "1". Accordingly, set the wait time fit for the oscillation stabilization time of the oscillator to be used. f(XIN)/16 is forcibly connected to the input of prescaler 12. When an external interrupt is accepted, oscillation is restarted but the internal clock f remains at "H" until timer 1 underflows. As soon as timer 1 underflows, the internal clock f is supplied. This is because when a ceramic oscillator is used, some time is required until a start of oscillation. In case oscillation is restarted by reset, no wait time is generated. So apply an "L" level to the RESET pin while oscillation becomes stable.

Wait mode

If the WIT instruction is executed, the internal clock f stops at an "H" level, but the oscillator does not stop. The internal clock restarts if a reset occurs or when an interrupt is received. Since the oscillator does not stop, normal operation can be started immediately after the clock is restarted. To ensure that interrupts will be received to release the STP or WIT state, interrupt enable bits must be set to "1" before the STP or WIT instruction is executed.

When the STP status is released, prescaler 12 and timer 1 will start counting clock which is XIN divided by 16, so set the timer 1 interrupt enable bit to "0" before the STP instruction is executed.

Note

For use with the oscillation stabilization set bit after release of the STP instruction set to "1", set values in timer 1 and prescaler 12 after fully appreciating the oscillation stabilization time of the oscillator to be used.

Switch of ceramic and CR oscillations

After releasing reset the operation starts by starting a built-in ring oscillator. Then, a ceramic oscillation or a CR oscillation is selected by setting bit 5 of the CPU mode register.

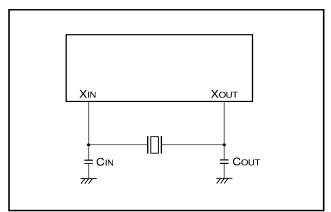
The bit 5 can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

●Double-speed mode

When a ceramic oscillation is selected, a double-speed mode can be used. Do not use it when a CR oscillation is selected.



7531 Group



MISRG(address 003816, initial value: 0016)

Oscillation stabilization time set bit after release of the STP instruction
0: Set "0116" in timer1, and "FF16" in prescaler 12 automatically
1: Not set automatically
1: Not set automatically
Reserved bits (return "0" when read)
(Do not write "1" to these bits)

Not used (return "0" when read)

Fig. 38 External circuit of ceramic resonator

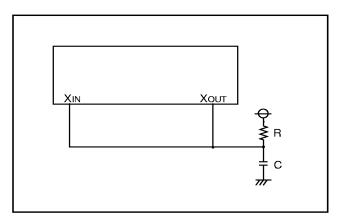


Fig. 39 External circuit of CR oscillation

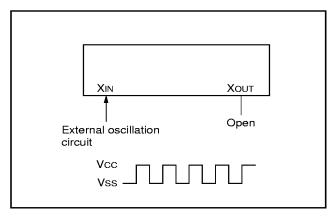


Fig. 40 External clock input circuit



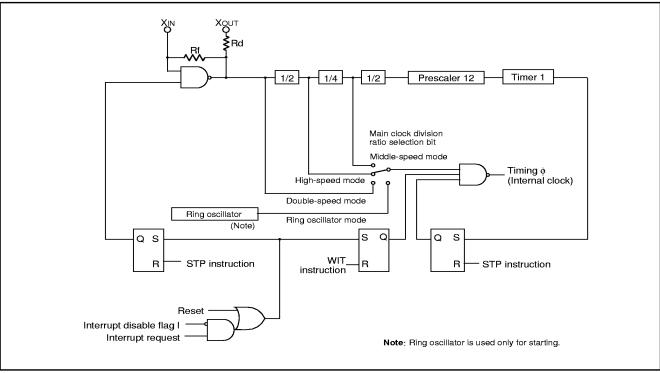


Fig. 42 Block diagram of internal clock generating circuit (for ceramic resonator)

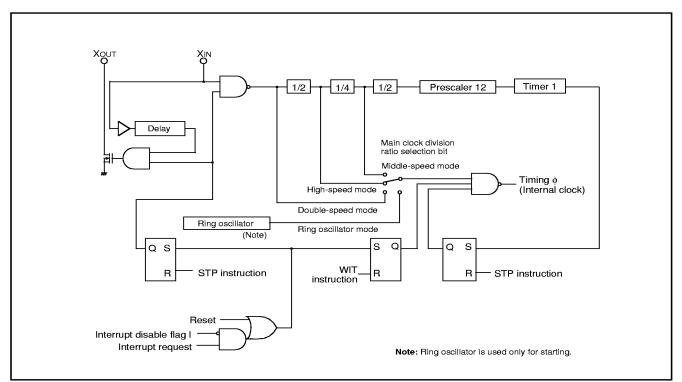


Fig. 43 Block diagram of internal clock generating circuit (for CR oscillation)



NOTES ON PROGRAMMING

Processor Status Register

The contents of the processor status register (PS) after reset are undefined except for the interrupt disable flag I which is "1". After reset, initialize flags which affect program execution. In particular, it is essential to initialize the T flag and the D flag because of their effect on calculations.

Interrupts

The contents of the interrupt request bit do not change even if the BBC or BBS instruction is executed immediately after they are changed by program because this instruction is executed for the previous contents. For executing the instruction for the changed contents, execute one instruction before executing the BBC or BBS instruction

Decimal Calculations

- For calculations in decimal notation, set the decimal mode flag D to "1", then execute the ADC instruction or SBC instruction. In this case, execute SEC instruction, CLC instruction or CLD instruction after executing one instruction before the ADC instruction or SBC instruction.
- In the decimal mode, the values of the N (negative), V (overflow) and Z (zero) flags are invalid.

Timers

- When n (0 to 255) is written to a timer latch, the frequency division ratio is 1/(n+1).
- When a count source of timer X is switched, stop a count of timer X.

Ports

- The values of the port direction registers cannot be read.
- That is, it is impossible to use the LDA instruction, memory operation instruction when the T flag is "1", addressing mode using direction register values as qualifiers, and bit test instructions such as BBC and BBS.
- It is also impossible to use bit operation instructions such as CLB and SEB and read/modify/write instructions of direction registers for calculations such as ROR.
- For setting direction registers, use the LDM instruction, STA instruction, etc.
- Set "1" to each bit 6 of the port P3 direction register and the port P3 register.

A-D Converter

The comparator uses internal capacitors whose charge will be lost if the clock frequency is too low.

Make sure that f(X_{IN}) is 500kHz or more during A-D conversion. Do not execute the STP instruction during A-D conversion.

Instruction Execution Timing

The instruction execution time can be obtained by multiplying the frequency of the internal clock ϕ by the number of cycles mentioned in the machine-language instruction table.

The frequency of the internal clock ϕ is the same as that of the XIN in double-speed mode, twice the XIN cycle in high-speed mode and 8 times the XIN cycle in middle-speed mode.

CPU Mode Register

The oscillation mode selection bit can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

When a ceramic oscillation is selected, a double-speed mode of the clock division ratio selection bits can be used. Do not use it when a CR oscillation is selected.

NOTES ON USE

Handling of Power Source Pin

In order to avoid a latch-up occurrence, connect a capacitor suitable for high frequencies as bypass capacitor between power source pin (Vcc pin) and GND pin (Vss pin). Besides, connect the capacitor to as close as possible. For bypass capacitor which should not be located too far from the pins to be connected, a ceramic capacitor of 0.01 μF to 0.1 μF is recommended.

One Time PROM Version

The CNVss pin is connected to the internal memory circuit block by a low-ohmic resistance, since it has the multiplexed function to be a programmable power source pin (VPP pin) as well.

To improve the noise reduction, connect a track between CNVss pin and Vss pin with 1 to 10 $\rm k\Omega$ resistance.

The mask ROM version track of CNVss pin has no operational interference even if it is connected via a resistor.



DATA REQUIRED FOR MASK ORDERS

The following are necessary when ordering a mask ROM production:

- (1) Mask ROM Order Confirmation Form
- (2) Mark Specification Form
- (3) Data to be written to ROM, in EPROM form (three identical copies)

DATA REQUIRED FOR ROM PROGRAMMING ORDERS

The following are necessary when ordering a ROM writing:

- (1) ROM Programming Confirmation Form
- (2) Mark Specification Form (for Special Mark)
- (3) Data to be written to ROM, in EPROM form (three identical copies)

ROM PROGRAMMING METHOD

The built-in PROM of the blank One Time PROM version can be read or programmed with a general-purpose PROM programmer using a special programming adapter. Set the address of PROM programmer in the user ROM area.

Table 5 Special programming adapter

Package	Name of Programming Adapter
32P4B	PCA7435SP
32P6B-A	PCA7435GP
36P2R-A	PCA7435FP

The PROM of the blank One Time PROM version is not tested or screened in the assembly process and following processes. To ensure proper operation after programming, the procedure shown in Figure 44 is recommended to verify programming.

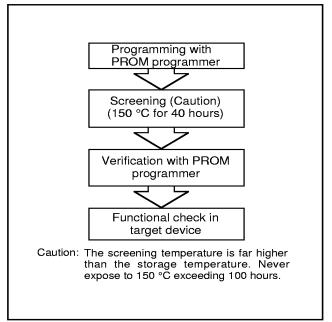


Fig. 44 Programming and testing of One Time PROM version



ELECTRICAL CHARACTERISTICS

1.7531Group (General purpose)

Applied to: M37531M4-XXXFP/SP/GP, M37531M8-XXXFP/SP/GP, M37531E4FP/SP/GP, M37531E8FP/SP

Absolute Maximum Ratings (General purpose)

Table 6 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit	
Vcc	Power source volta	age		-0.3 to 7.0		
Vı	Input voltage P00–P07, P10–P14, P20–P27, P30–P37, VREF		All voltages are	-0.3 to Vcc + 0.3	V	
Vı	Input voltage	RESET, XIN	based on Vss.	-0.3 to Vcc + 0.3	V	
Vı	Input voltage	CNVss (Note 1)	Output transistors are cut off.	-0.3 to 13	V	
Vo	Output voltage	P00–P07, P10–P14, P20–P27, P30–P37, XOUT	1	-0.3 to Vcc + 0.3	V	
Pd	Power dissipation		Ta = 25°C	300 (Note 2)	mW	
Topr	Operating tempera	ture		-20 to 85	°C	
Tstg	Storage temperatu	re	7	-40 to 125	°C	

Note 1: It is a rating only for the One Time PROM version. Connect to Vss for the mask ROM version. 2: 200 mW for the 32P6B package product.



Recommended Operating Conditions (General purpose)

Table 7 Recommended operating conditions (1) (Vcc = 2.2 to 5.5 V, Ta = -20 to 85 °C, unless otherwise noted)

Symbol	Pore	Parameter		Limits			Unit
Symbol	Para	ameter		Min.	Тур.	Max.	Unit
Vcc	Power source voltage (ceramic) f((XIN) =	8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
	f((XIN) =	4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	٧
	f((XIN) = :	2 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	٧
	f(.	(XIN) =	4 MHz (Double-speed mode)	4.0	5.0	5.5	V
	f(.	(XIN) =	2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	f(.	(XIN) =	1 MHz (Double-speed mode)	2.2	5.0	5.5	٧
	Power source voltage (CR) f((XIN) =	4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		(XIN) =	2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		(XIN) =	1 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	V
Vss	Power source voltage				0		V
VREF	Analog reference voltage			2.0		Vcc	V
ViH	"H" input voltage		P00–P07, P10–P14, P20–P27, P30–P37	0.8Vcc		Vcc	٧
ViH	"H" input voltage (TTL input level selected)		P10, P12, P13, P36, P37 (Note 1)	2.0		Vcc	V
VIH	"H" input voltage		RESET, XIN	0.8Vcc		Vcc	V
VIL	"L" input voltage		P00–P07, P10–P14, P20–P27, P30–P37	0		0.3Vcc	V
VIL	"L" input voltage (TTL input level select	ted)	P10, P12, P13, P36, P37 (Note 1)	0		0.8	V
VIL	"L" input voltage		RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage		XIN	0		0.16Vcc	V
\sum IOH(peak)	"H" total peak output current (Note 2)		P00-P07, P10-P14, P20-P27, P30-P37			-80	mA
∑IOL(peak)	"L" total peak output current (Note 2)		P00–P07, P10–P14, P20–P27, P37			80	mA
∑lOL(peak)	"L" total peak output current (Note 2)		P30-P36			60	mA
∑lOH(avg)	"H" total average output current (Note 2	2)	P00–P07, P10–P14, P20–P27, P30–P37			-40	mA
∑lOL(avg)	"L" total average output current (Note 2	2)	P00-P07, P10-P14, P20-P27, P37			40	mA
∑lOL(avg)	"L" total average output current (Note 2	2)	P30-P36			30	mA

Note 1: Vcc = 4.0 to 5.5V



^{2:} The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Recommended Operating Conditions (General purpose)(continued)

Table 8 Recommended operating conditions (2) (Vcc = 2.2 to 5.5 V, Ta = -20 to 85 °C, unless otherwise noted)

0	D	_		Limits		Unit
Symbol	Parameter		Min.	Тур.	Max.	7 Unit
IOH(peak)	"H" peak output current (Note 1)	P00-P07, P10-P14, P20-P27, P30-P37			-10	mA
IOL(peak)	"L" peak output current (Note 1)	P00–P07, P10–P14, P20–P27, P37			10	mA
IOL(peak)	"L" peak output current (Note 1)	P30-P36			30	mA
IOH(avg)	"H" average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			– 5	mA
IOL(avg)	"L" average output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			5	mA
IOL(avg)	"L" average output current (Note 2)	P30-P36			15	mA
f(XIN) li	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 4.0 to 5.5 V Double-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.4 to 5.5 V Double-speed mode			2	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.2 to 5.5 V Double-speed mode			1	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	VCC = 2.2 to 5.5 V High-, Middle-speed mode			2	MHz
	Internal clock oscillation frequency (Note 3) at CR oscillation	VCC = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at CR oscillation	VCC = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz
	Internal clock oscillation frequency (Note 3) at CR oscillation	VCC = 2.2 to 5.5 V High-, Middle-speed mode			1	MHz



Notes 1: The peak output current is the peak current flowing in each port.
2: The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.
3: When the oscillation frequency has a duty cycle of 50 %.

Electrical Characteristics (General purpose)

Table 9 Electrical characteristics (Vcc = 2.2 to 5.5 V, Vss = 0 V, Ta = -20 to 85 $^{\circ}$ C, unless otherwise noted)

Symbol		Para	ameter	Testic	onditions		Limits		Unit
Cyllibol		ı ar		1631.6		Min.	Тур.	Max.	0,,,,
Vон	"H" output voltage		907, P10–P14, P20–P27, 937 (Note 1)	IOH = -5 m VCC = 4.0		Vcc-1.5			
				IOH = -1.0 VCC = 2.2		Vcc-1.0			V
Vol	"L" output voltage	P00-F P37	907, P10–P14, P20–P27,	IOL = 5 mA VCC = 4.0				1.5	V
				IOL = 1.5 n VCC = 4.0				0.3	V
				IOL = 1.0 n VCC = 2.2				1.0	V
Vol	"L" output voltage	P30-F	236	IOL = 15 m VCC = 4.0				2.0	٧
				IOL = 1.5 n VCC = 4.0				0.3	٧
				IOL = 10 m VCC = 2.2				1.0	V
VT+-VT-	Hysteresis	CNTRo, INTo, INT1(Note 2) P00–P07 (Note 3) RXD, SCLK, SDATA (Note 2) RESET nt P00–P07, P10–P14, P20–P27, P30–P37					0.4		V
VT+-VT-	Hysteresis	RxD,	SCLK, SDATA (Note 2)				0.5		V
VT+-VT-	Hysteresis	sis RESET					0.5		V
lін	"H" input current	P00-P07, P10-P14, P20-P27,		VI = VCC (Pin floatin transistors				5.0	μА
liн	"H" input current	H" input current RESET			•			5.0	μА
liн	"H" input current	XIN	·	VI = VCC			4.0		μА
liL	"L" input current	P00-F	.IN 00–P07, P10–P14, P20–P27, 30–P37		ig. Pull up "off")			-5.0	μА
lıL	"L" input current	BESE	T, CNVss	VI = VSS	•			-5.0	μА
lıL	"L" input current	XIN	1, 011100	VI = VSS			-4.0		μА
lıL	"L" input current		207, P30–P37	VI = VSS (Pull up trai	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When clos	k stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.2 V		0.5	1.5	mA
			Double-speed mode, f(XIN Output transistors "off") = 4 MHz			5.0	8.0	mA
		Middle-speed mode, f(XIN) Output transistors "off" f(XIN) = 8 MHz (in WIT state) Output transistors "off"		= 8 MHz			2.0	5.0	mA
				te)			1.6	3.2	mA
			f(XIN) = 2 MHz, Vcc = 2.2 Output transistors "off"	V (in WIT sta	te)		0.2		mA
			Increment when A-D conve f(XIN) = 8 MHz, VCC = 5 V	ersion is exec	cuted		0.5		mA
				tion stopped (in STP state) Ta = 25 °C			0.1	1.0	μА
			Output transistors "off"	Ta = 85 °C				10	μА

^{3:} It is available only when operating key-on wake up.



Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

2: RxD, Sclk, SDATA, INTo, and INT1 have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

A-D Converter Characteristics (General purpose)

Table 10 A-D Converter characteristics (1) (Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Strongle at	Parameter	Took conditions		Limits		Unit
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	
_	Resolution				10	Bits
_	Absolute accuracy (excluding quantization error)	Vcc = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
_	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	m∨
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tconv	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μА
		VREF = 3.0 V	30	70	120	Τ μΛ
li(AD)	A-D port input current				5.0	μА



Timing Requirements (General purpose)

Table 11 Timing requirements (1) (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -20 to 85 $^{\circ}$ C, unless otherwise noted)

C b - 1	Davida da la companya		Limits		السال
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	2			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twL(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTRo input cycle time	200			ns
twh(CNTR)	CNTRo, INTo, INT1, input "H" pulse width	80			ns
twL(CNTR)	CNTRo, INTo, INT1, input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	400			ns
twL(Sclk)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 12 Timing requirements (2) (Vcc = 2.2 to 5.5 V or 2.4 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Course and	Parameter			Limits		
Symbol	Parameter		Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width		2			μs
tc(XIN)	External clock input cycle time	Vcc = 2.2 to 5.5 V	500			ns
		VCC = 2.4 to 5.5 V	250			ns
twh(XIN)	External clock input "H" pulse width	Vcc = 2.2 to 5.5 V	200			ns
		Vcc = 2.4 to 5.5 V	100			ns
twL(XIN)	External clock input "L" pulse width	Vcc = 2.2 to 5.5 V	200			ns
		VCC = 2.4 to 5.5 V	100			ns
tc(CNTR)	CNTRo input cycle time	Vcc = 2.2 to 5.5 V	1000			ns
		Vcc = 2.4 to 5.5 V	500			ns
twh(CNTR)	CNTRo, INTo, INT1, input "H" pulse width	Vcc = 2.2 to 5.5 V	460			ns
		VCC = 2.4 to 5.5 V	230			ns
twL(CNTR)	CNTRo, INTo, INT1, input "L" pulse width	Vcc = 2.2 to 5.5 V	460			ns
		Vcc = 2.4 to 5.5 V	230			ns
tc(Sclk)	Serial I/O2 clock input cycle time	Vcc = 2.2 to 5.5 V	4000			ns
		VCC = 2.4 to 5.5 V	2000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	Vcc = 2.2 to 5.5 V	1900			ns
		Vcc = 2.4 to 5.5 V	950			ns
twL(Sclk)	Serial I/O2 clock input "L" pulse width	Vcc = 2.2 to 5.5 V	1900			ns
		Vcc = 2.4 to 5.5 V	950			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	•	400			ns
th(SCLK-SDATA)	Serial I/O2 input hold time		400			ns



Switching Characteristics (General purpose)

Table 13 Switching characteristics (1) (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Comment of	Devenuetor	L	imits		Unit
Symbol	Parameter	Min.	Тур.	140 30 30	1 Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(ScLK)/2-30			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(ScLK)/2-30			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			140	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			30	ns
tr(Sclk)	Serial I/O2 clock output falling time			30	ns
tr(CMOS)	CMOS output rising time (Note 1)		10	30	ns
tf(CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XouT is excluded.

Table 14 Switching characteristics (2) (Vcc = 2.2 to 5.5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Completed	Parameter	Lii		Unit	
Symbol	Parameter	Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-50			ns
twL(ScLK)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-50			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			350	ns
tv(SCLK–SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			50	ns
tf(SCLK)	Serial I/O2 clock output falling time			50	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	50	ns
tf(CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin Xout is excluded.

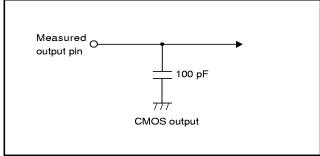


Fig. 45 Switching characteristics measurement circuit diagram (General purpose)



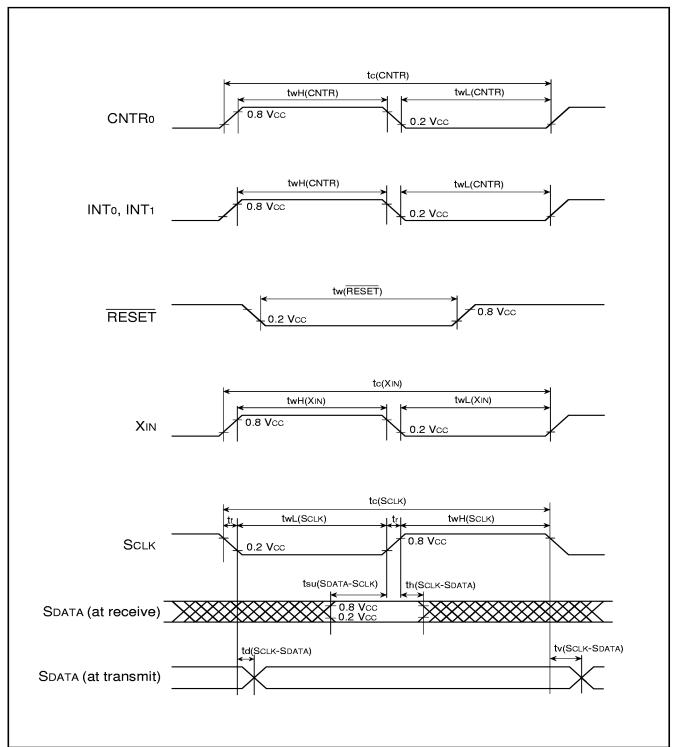


Fig. 46 Timing chart (General purpose)



2.7531Group (Extended operating temperature version)

Applied to: M37531M4T-XXXGP, M37531E4T-XXXGP

Absolute Maximum Ratings (Extended operating temperature version)

Table 15 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit
Vcc	Power source volta	age		-0.3 to 7.0	V
Vı	Input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37, VREF	All voltages are	-0.3 to Vcc + 0.3	V
Vi	Input voltage	RESET, XIN	based on Vss. Output transistors	-0.3 to Vcc + 0.3	V
Vı	Input voltage	CNVss (Note 1)	are cut off.	-0.3 to 13	V
Vo	Output voltage	P00–P07, P10–P14, P20–P25, P30–P34, P37, XOUT		-0.3 to Vcc + 0.3	V
Pd	Power dissipation		Ta = 25°C	200	mW
Topr	Operating tempera	Operating temperature		-40 to 85	°C
Tstg	Storage temperatu	Storage temperature		-65 to 150	°C

Note 1: It is a rating only for the One Time PROM version. Connect to Vss for the mask ROM version.



Recommended Operating Conditions (Extended operating temperature version)

Table 16 Recommended operating conditions (1) (VCC = 2.4 to 5.5 V. Ta = -40 to 85 °C. unless otherwise noted)

Comple al		Davamatav		Limits		Unit
Symbol		Parameter	Min.	Тур.	Max.	Uni
Vcc	Power source voltage (ceramic)	f(XIN) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	٧
		f(XIN) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(XIN) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	٧
		f(XIN) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(XIN) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
Vss	Power source voltage			0		V
VREF	Analog reference voltage	nalog reference voltage				V
ViH	"H" input voltage	P00–P07, P10–P14, P20–P25, P30–P34, P37	0.8Vcc		Vcc	٧
VIH	"H" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)			Vcc	٧
ViH	"H" input voltage	RESET, XIN	0.8Vcc		Vcc	V
VIL	"L" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0		0.3Vcc	V
VIL	"L" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)	0		0.8	٧
VIL	"L" input voltage	RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage	XIN	0		0.16Vcc	٧
\sum lOH(peak)	"H" total peak output current (Note 2)	P00–P07, P10–P14, P20–P25, P30–P34, P37			-80	mA
∑lOL(peak)	"L" total peak output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			80	mA
∑lOL(peak)	"L" total peak output current (Note 2)	P30-P34			60	mA
∑lOH(avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P25, P30-P34, P37			-40	m/
∑lOL(avg)	"L" total average output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			40	m/
∑lOL(avg)	"L" total average output current (Note 2)	P30-P34			30	mA



Note 1: Vcc = 4.0 to 5.5V

2: The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Recommended Operating Conditions (Extended operating temperature version) (continued)

Table 17 Recommended operating conditions (2) (Vcc = 2.4 to 5.5 V, Ta = -40 to 85 °C, unless otherwise noted)

Courselle and	Parameter			Limits		Unit
Symbol	Parameter		Min.	Тур.	Max.	1 Unit
IOH(peak)	"H" peak output current (Note 1) P00-P07,	P10-P14, P20-P25, P30-P34, P37			-10	mA
IOL(peak)	"L" peak output current (Note 1) P00-P07,	P10-P14, P20-P25, P37			10	mA
IOL(peak)	"L" peak output current (Note 1) P30-P34				30	mA
IOH(avg)	"H" average output current (Note 2) P00-P07,	P10-P14, P20-P25, P30-P34, P37			-5	mA
IOL(avg)	"L" average output current (Note 2) P00-P07,	average output current (Note 2) P00-P07, P10-P14, P20-P25, P37				mA
IOL(avg)	"L" average output current (Note 2) P30-P34			15	mA	
f(XIN)	· · · · · · · · · · · · · · · · · · ·	Vcc = 4.0 to 5.5 V Double-speed mode			4	MHz
		Vcc = 2.4 to 5.5 V Double-speed mode			2	MHz
		Vcc = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	· · · · · · · · · · · · · · · · · · ·	VCC = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	· · · · · · · · · · · · · · · · · · ·	VCC = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
		Vcc = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz



Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

Electrical Characteristics (Extended operating temperature version)

Table 18 Electrical characteristics (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Symbol Parameter T					Limits		Τ		
Symbol		Para	meter	l est c	onditions	Min.	Тур.	Max.	Unit
Vон	"H" output voltage		07, P10–P14, P20–P25, 34 (Note 1)	IOH = -5 m VCC = 4.0		Vcc-1.5			٧
				IOH = -1.0 VCC = 2.4		Vcc-1.0			٧
Vol	"L" output voltage	P00-F P37	07, P10–P14, P20–P25,	IOL = 5 mA VCC = 4.0				1.5	٧
				IOL = 1.5 m VCC = 4.0				0.3	V
				IOL = 1.0 m VCC = 2.4				1.0	٧
Vol	"L" output voltage	P30-F	34	IOL = 15 m VCC = 4.0				2.0	٧
				IOL = 1.5 m VCC = 4.0				0.3	٧
				IOL = 10 m VCC = 2.4				1.0	V
VT+-VT-	Hysteresis		o, INTo (Note 2) 07 (Note 3)				0.4		V
$V_{T+}-V_{T-}$	Hysteresis	RxD, S	SCLK, SDATA (Note 2)				0.5		V
$V_{T+}-V_{T-}$	Hysteresis	RESE	Т				0.5		V
Іін	"H" input current		07, P10–P14, P20–P25, 34, P37	VI = VCC (Pin floatin transistors				5.0	μА
lін	"H" input current	RESE	T	VI = VCC				5.0	μА
liн	"H" input current	XIN		VI = VCC			4.0		μА
lıL	"L" input current			VI = VSS (Pin floatin transistors				- 5.0	μА
lıL	"L" input current	RESE	T, CNVss	VI = VSS				-5.0	μА
lıL	"L" input current	XIN	•	Vı = Vss			-4.0		μА
liL	"L" input current	P00-F	07, P30–P34, P37	VI = VSS (Pull up trar	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When cloc	k stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.4 V		0.5	1.5	mA
			Double-speed mode, f(XIN) Output transistors "off"	= 4 MHz			5.0	8.0	mA
			Middle-speed mode, f(XIN) Output transistors "off"	= 8 MHz,			2.0	5.0	mA
			f(XIN) = 8 MHz (in WIT state Functions except Timer 1 a Output transistors "off"	e) und Timer 2 s	stop		1.6	3.2	mA
			f(XIN) = 2 MHz, Vcc = 2.4 V Output transistors "off"	/ (in WIT sta	te)		0.2		mA
			Increment when A-D conve f(XIN) = 8 MHz, Vcc = 5 V	ersion is exec	cuted		0.5		mA
			All oscillation stopped (in S	TP state)	Ta = 25 °C		0.1	1.0	μА
			Output transistors "off"	-	Ta = 85 °C			10	μА

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

2: RxD, Sclk, SDATA, and INTo have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

3: It is available only when operating key-on wake up.



A-D Converter Characteristics (Extended operating temperature version)

Table 19 A-D Converter characteristics (1) (Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Comment of	Parameter	Test conditions		Limits		Unit
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	
_	Resolution				10	Bits
_	Absolute accuracy (excluding quantization error)	Vcc = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
_	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tconv	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μА
		VREF = 3.0 V	30	70	120	1 μΛ
lı(AD)	A-D port input current				5.0	μА



Timing Requirements (Extended operating temperature version)

Table 20 Timing requirements (1) (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 85 $^{\circ}$ C, unless otherwise noted)

0 1 1	В .		Limits		T
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	2			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twL(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTRo input cycle time	200			ns
twn(CNTR)	CNTRo, INTo input "H" pulse width	80			ns
twL(CNTR)	CNTRo, INTo input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twн(Sclk)	Serial I/O2 clock input "H" pulse width	400			ns
twL(Sclk)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 21 Timing requirements (2) (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

O	D		Limits		J
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	2			μs
tc(XIN)	External clock input cycle time	250			ns
twn(XIN)	External clock input "H" pulse width	100			ns
twL(XIN)	External clock input "L" pulse width	100			ns
tc(CNTR)	CNTRo input cycle time	500			ns
twn(CNTR)	CNTRo, INTo input "H" pulse width	230			ns
twL(CNTR)	CNTRo, INTo input "L" pulse width	230			ns
tc(Sclk)	Serial I/O2 clock input cycle time	2000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	950			ns
twL(Sclk)	Serial I/O2 clock input "L" pulse width	950			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	400			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	400			ns



Switching Characteristics (Extended operating temperature version)

Table 22 Switching characteristics (1) (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Committee and	Parameter	L	imits	Max.	11
Symbol	Parameter	Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-30			ns
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-30			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			140	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			30	ns
tr(Sclk)	Serial I/O2 clock output falling time			30	ns
tr(CMOS)	CMOS output rising time (Note 1)		10	30	ns
tr(CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XouT is excluded.

Table 23 Switching characteristics (2) (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Completed	Parameter	Li	mits	350	1114
Symbol	Parameter	Min.	Typ. Max.	Unit	
twн(ScLK)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-50			ns
twL(ScLK)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-50			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			350	ns
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			50	ns
tf(SCLK)	Serial I/O2 clock output falling time			50	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	50	ns
tr(CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin Xout is excluded.

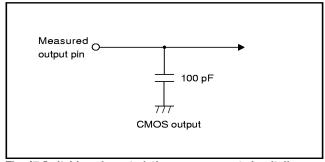


Fig. 47 Switching characteristics measurement circuit diagram (Extended operating temperature version)



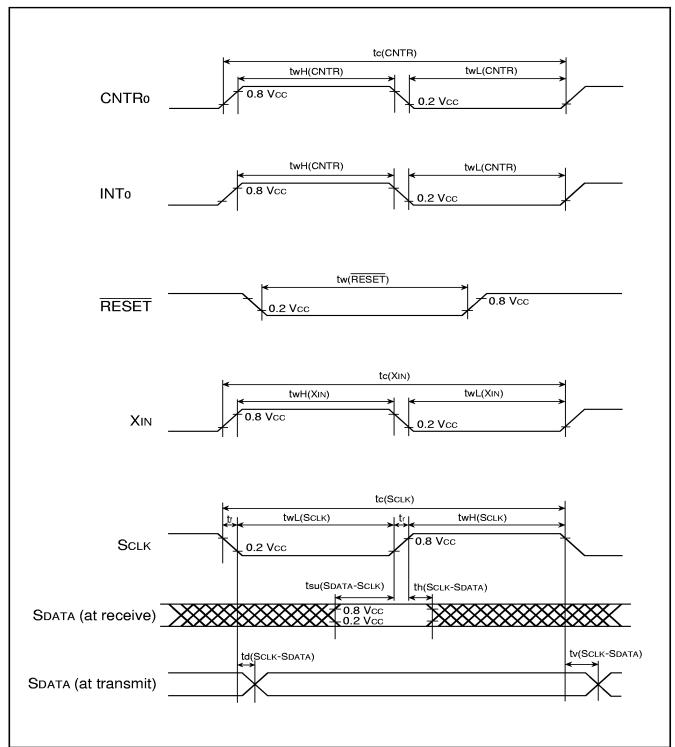


Fig. 48 Timing chart (Extended operating temperature version)



3.7531Group (Extended operating temperature 125 °C version)

Applied to: M37531M4V-XXXGP, M37531E4V-XXXGP

Absolute Maximum Ratings (Extended operating temperature 125 °C version)

Table 24 Absolute maximum ratings

Symbol		Parameter	Conditions	Ratings	Unit
Vcc	Power source volta	age		-0.3 to 7.0	V
Vı	Input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37, VREF	All voltages are based on VSS. Output transistors are cut off.	-0.3 to Vcc + 0.3	V
Vı	Input voltage	RESET, XIN		-0.3 to Vcc + 0.3	V
Vı	Input voltage	CNVss (Note 1)		-0.3 to 13	V
Vo	Output voltage	P00–P07, P10–P14, P20–P25, P30–P34, P37, XOUT		-0.3 to Vcc + 0.3	٧
Pd	Power dissipation		Ta = 25°C	200	mW
Topr	Operating tempera	Operating temperature (Note 2)		-40 to 125	°C
Tstg	Storage temperatu	ıre	│	-65 to 150	°C

Notes 1: It is a rating only for the One Time PROM version. Connect to Vss for the mask ROM version.

2: The total time is limited as follows: 6000 hours at 55 to 85 °C, 1000 hours at 85 to 125 °C



Recommended Operating Conditions (Extended operating temperature 125 °C version)

Table 25 Recommended operating conditions (1) (VCC = 2.4 to 5.5 V, Ta = -40 to 125 °C, unless otherwise noted)

Comple al		Davamatav		Limits		Unit
Symbol		Parameter	Min.	Тур.	Max.	Uni
Vcc	Power source voltage (ceramic)	f(XIN) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	٧
		f(XIN) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	٧
		f(XIN) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(XIN) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(XIN) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
Vss	Power source voltage	·		0		V
VREF	Analog reference voltage	ŭ .			Vcc	V
ViH	"H" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0.8Vcc		Vcc	V
VIH	"H" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)	2.0		Vcc	\ \
ViH	"H" input voltage	RESET, XIN	0.8Vcc		Vcc	V
VIL	"L" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0		0.3Vcc	V
VIL	"L" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)	0		0.8	٧
VIL	"L" input voltage	RESET, CNVss	0		0.2Vcc	V
VIL	"L" input voltage	XIN	0		0.16Vcc	V
\sum lOH(peak)	"H" total peak output current (Note 2)	P00-P07, P10-P14, P20-P25, P30-P34, P37			-80	mA
∑lOL(peak)	"L" total peak output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			80	mA
∑lOL(peak)	"L" total peak output current (Note 2)	P30-P34			60	mA
∑lOH(avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P25, P30-P34, P37			-40	m/
∑lOL(avg)	"L" total average output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			40	m/
∑lOL(avg)	"L" total average output current (Note 2)	P30-P34			30	mA



Note 1: Vcc = 4.0 to 5.5V

2: The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Recommended Operating Conditions (Extended operating temperature 125 °C version) (continued)

Table 26 Recommended operating conditions (2) (Vcc = 2.4 to 5.5 V, Ta = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
Symbol	Farameter		Min.	Тур.	Max.	
IOH(peak)	"H" peak output current (Note 1) P00-P07	, P10–P14, P20–P25, P30–P34, P37			-10	mA
IOL(peak)	"L" peak output current (Note 1) P00-P07	" peak output current (Note 1) P00-P07, P10-P14, P20-P25, P37			10	mA
IOL(peak)	." peak output current (Note 1) P30–P34				30	mA
IOH(avg)	"H" average output current (Note 2) P00-P07	" average output current (Note 2) P00–P07, P10–P14, P20–P25, P30–P34, P3			- 5	mA
IOL(avg)	"L" average output current (Note 2) P00-P07	r, P10–P14, P20–P25, P37			5	mA
IOL(avg)	"L" average output current (Note 2) P30-P34	"L" average output current (Note 2) P30-P34			15	mA
f(XIN)	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V Double-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V Double-speed mode			2	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Internal clock oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at CR oscillation	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Internal clock oscillation frequency (Note 3) at CR oscillation	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz



Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current IoL (avg), IoH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

Electrical Characteristics (Extended operating temperature 125 °C version)

Table 27 Electrical characteristics (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

0		Б		T1-			Limits		1.1
Symbol		Para	ameter	l est c	onditions	Min.	Тур.	Max.	Unit
Vон	"H" output voltage		707, P10-P14, P20-P25, 934 (Note 1)	IOH = -5 m VCC = 4.0		Vcc-1.5			٧
				IOH = -1.0 VCC = 2.4		Vcc-1.0			V
Vol	"L" output voltage	P00-F P37	207, P10–P14, P20–P25,	IOL = 5 mA VCC = 4.0				1.5	٧
				IOL = 1.5 m VCC = 4.0				0.3	٧
				IOL = 1.0 m VCC = 2.4				1.0	٧
Vol	"L" output voltage	P30-F	234	IOL = 15 m VCC = 4.0				2.0	V
				IOL = 1.5 m VCC = 4.0				0.3	٧
				IOL = 10 m VCC = 2.4				1.0	V
VT+-VT-	Hysteresis		0, INT0, (Note 2) 207 (Note 3)				0.4		٧
VT+-VT-	Hysteresis	RxD,	SCLK, SDATA (Note 2)				0.5		V
VT+-VT-	Hysteresis	RESE	Т				0.5		V
lін	"H" input current		907, P10–P14, P20–P25, 934, P37	VI = VCC (Pin floatin transistors				5.0	μА
liн	"H" input current	RESE	T	VI = VCC				5.0	μА
liн	"H" input current	XIN		VI = VCC			4.0		μΑ
lıL	"L" input current		907, P10–P14, P20–P25, P34, P37	VI = VSS (Pin floatin transistors				-5.0	μА
liL	"L" input current	RESE	T, CNVss	VI = VSS				-5.0	μА
lıL	"L" input current	XIN	•	Vı = Vss			-4.0		μА
lıL	"L" input current	P00-F	907, P30–P34, P37	VI = VSS (Pull up trar	nsistors "on")		-0.2	-0.5	mA
VRAM	RAM hold voltage			When cloc	k stopped	2.0		5.5	V
Icc	Power source curr	ent	High-speed mode, f(XIN) = Output transistors "off"	8 MHz			5.0	8.0	mA
			High-speed mode, f(XIN) = Output transistors "off"	2 MHz, Vcc	= 2.4 V		0.5	1.5	mA
			Double-speed mode, f(XIN) Output transistors "off"	= 4 MHz			5.0	8.0	mA
			Middle-speed mode, f(XIN) Output transistors "off"	= 8 MHz,			2.0	5.0	mA
			f(XIN) = 8 MHz (in WIT state Functions except Timer 1 a Output transistors "off"		top		1.6	3.2	mA
			f(XIN) = 2 MHz, Vcc = 2.4 \ Output transistors "off"	/ (in WIT stat	te)		0.2		mA
			Increment when A-D conve f(XIN) = 8 MHz, Vcc = 5 V	rsion is exec	uted		0.5		mA
			All oscillation stopped (in S	TP state)	Ta = 25 °C		0.1	1.0	μА
			Output transistors "off" TXD P-channel output disable		Ta = 125 °C			50	μА

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".

2: RxD, Sclk, SDATA, and INTo have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to "0" (CMOS level).

3: It is available only when operating key-on wake up.



A-D Converter Characteristics (Extended operating temperature 125 °C version)

Table 28 A-D Converter characteristics (1) (Vcc = 2.7 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Comments and	Parameter	Took oon diking		Limits		Unit	
Symbol	Parameter	Test conditions	Min.	Тур.	Max.		
_	Resolution				10	Bits	
_	Absolute accuracy (excluding quantization error)	Vcc = 2.7 to 5.5 V Ta = 25 °C			±3	LSB	
_	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB	
Vот	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV	
		VCC = VREF = 3.072 V	0	3	15	mV	
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV	
		VCC = VREF = 3.072 V	3060	3069	3075	mV	
tconv	Conversion time				122	tc(XIN)	
RLADDER	Ladder resistor			55		kΩ	
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μА	
		VREF = 3.0 V	30	70	120	٦ ٣ <u>^ </u>	
li(AD)	A-D port input current				5.0	μА	



Timing Requirements (Extended operating temperature 125 °C version)

Table 29 Timing requirements (1) (VCC = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

0 1 1	D .		Limits		
Symbol	Parameter	Min.	Тур.	Max.	Unit
tw(RESET)	Reset input "L" pulse width	2			μs
tc(XIN)	External clock input cycle time	125			ns
twh(XIN)	External clock input "H" pulse width	50			ns
twL(XIN)	External clock input "L" pulse width	50			ns
tc(CNTR)	CNTRo input cycle time	200			ns
twn(CNTR)	CNTRo, INTo input "H" pulse width	80			ns
twL(CNTR)	CNTRo, INTo input "L" pulse width	80			ns
tc(Sclk)	Serial I/O2 clock input cycle time	1000			ns
twн(ScLK)	Serial I/O2 clock input "H" pulse width	400			ns
twL(ScLK)	Serial I/O2 clock input "L" pulse width	400			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	200			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	200			ns

Table 30 Timing requirements (2) (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

0	D		Limits		11
Symbol	Parameter	Min.	Min. Typ. Max.	Unit	
tw(RESET)	Reset input "L" pulse width	2			μs
tc(XIN)	External clock input cycle time	250			ns
twn(XIN)	External clock input "H" pulse width	100			ns
tWL(XIN)	External clock input "L" pulse width	100			ns
tc(CNTR)	CNTRo input cycle time	500			ns
twn(CNTR)	CNTRo, INTo, input "H" pulse width	230			ns
twL(CNTR)	CNTRo, INTo, input "L" pulse width	230			ns
tc(Sclk)	Serial I/O2 clock input cycle time	2000			ns
twh(Sclk)	Serial I/O2 clock input "H" pulse width	950			ns
twl(Sclk)	Serial I/O2 clock input "L" pulse width	950			ns
tsu(SCLK-SDATA)	Serial I/O2 input set up time	400			ns
th(SCLK-SDATA)	Serial I/O2 input hold time	400			ns



Switching Characteristics (Extended operating temperature 125 °C version)

Table 31 Switching characteristics (1) (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Committee and	Developator	L	imits	nits		
Symbol	Parameter	Min.	Тур.	Max.	Unit	
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(ScLK)/2-50			ns	
twL(Sclk)	Serial I/O2 clock output "L" pulse width	tc(ScLK)/2-50			ns	
td(SCLK-SDATA)	Serial I/O2 output delay time			200	ns	
tv(SCLK-SDATA)	Serial I/O2 output valid time	0			ns	
tr(SCLK)	Serial I/O2 clock output rising time			50	ns	
tr(Sclk)	Serial I/O2 clock output falling time			50	ns	
tr(CMOS)	CMOS output rising time (Note 1)		10	50	ns	
tf(CMOS)	CMOS output falling time (Note 1)		10	50	ns	

Note 1: Pin XouT is excluded.

Table 32 Switching characteristics (2) (Vcc = 2.4 to 5.5 V, Vss = 0 V, Ta = -40 to 125 °C, unless otherwise noted)

Cy comb al	Parameter	Li	Unit		
Symbol	Parameter	Min.	Тур.	Max.	Unit
twh(Sclk)	Serial I/O2 clock output "H" pulse width	tc(Sclk)/2-80			ns
twL(ScLK)	Serial I/O2 clock output "L" pulse width	tc(Sclk)/2-80			ns
td(SCLK-SDATA)	Serial I/O2 output delay time			400	ns
tv(SCLK–SDATA)	Serial I/O2 output valid time	0			ns
tr(SCLK)	Serial I/O2 clock output rising time			80	ns
tf(SCLK)	Serial I/O2 clock output falling time			80	ns
tr(CMOS)	CMOS output rising time (Note 1)		20	80	ns
tr(CMOS)	CMOS output falling time (Note 1)		20	80	ns

Note 1: Pin Xout is excluded.

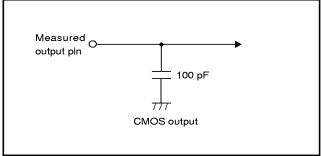


Fig. 49 Switching characteristics measurement circuit diagram (Extended operating temperature 125 °C version)



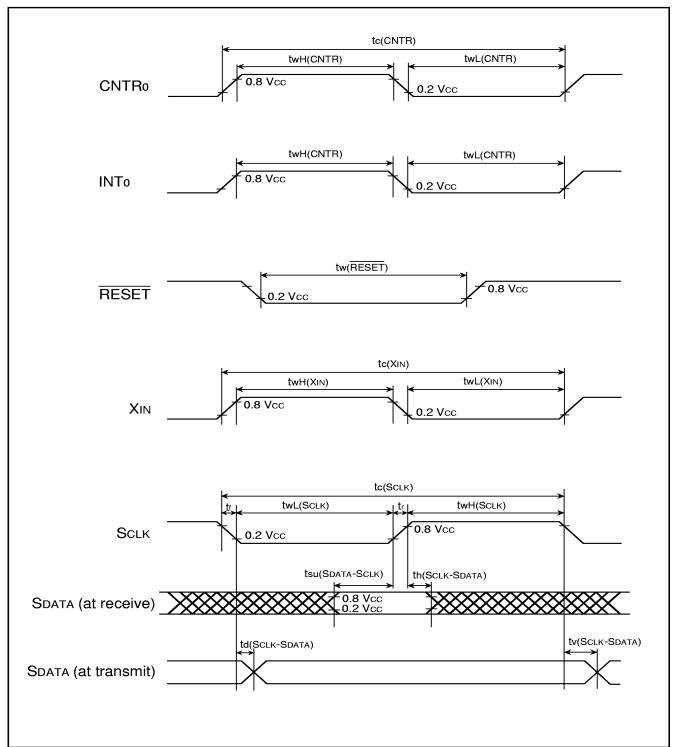


Fig. 50 Timing chart (Extended operating temperature 125 °C version)



MASK ROM CONFIRMATION FORM

GZZ-SH52-89B<85B0>

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4-XXXFP/GP/SP MITSUBISHI ELECTRIC

Mask ROM number	

	Date:	
<u>.</u>	Section head	Supervisor
ei D	signature	signature
3eceipt		
ш		

Note: Please fill in all items marked *.

		Company		TEL		о Ф	Submitted by	Supervisor
*	Customer	name		()	uano natur		
	Date issued	Date:			Issi Sigi			

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

☐ M37531M4-XXXFP ☐ M37531M4-XXXGP

|--|

Checksum code for entire EPROM			(hexadecimal notatio

EPROM type (indicate the type used)

Microcomputer name:

	27C256		27C512
EPROM ac	ddress	EPROM ac	ddress
000016	Area for ASCII codes of the name of the product	000016	Area for ASCII codes of the name of the product 'M37531M4'
000F ₁₆ 0010 ₁₆		000F ₁₆ 0010 ₁₆	
607F ₁₆		E07F ₁₆	
608016	Data Data	E080 ₁₆	Data
7FFD16 7FFE16 7FFF16	ROM (8K–130) bytes	FFFD16 FFFE16 FFFF16	ROM (8K–130) bytes

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

☐ M37531M4-XXXSP

- (1) Set "FF $_{16}$ " in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M4-' to addresses 000016 to 000F16. ASCII codes 'M37531M4-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D16	0008 16	' – ' = 2D ₁₆
000116	'3' = 33 16	0009 16	FF16
000216	'7' = 37 16	000A 16	FF ₁₆
000316	'5' = 35 ₁₆	000B 16	FF16
000416	'3' = 33 16	000C 16	FF ₁₆
000516	'1' = 31 16	000D 16	FF ₁₆
0006 16	'M' = 4D16	000 E ₁₆	FF16
000716	'4' = 34 ₁₆	000F 16	FF16

(1/2)



SINGI F-C	HIP 8-BIT	CMOS	MICROC	OMPLITE	₹

GZZ-SH52-89B<85B0>

Mask ROM number	
-----------------	--

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4-XXXFP/GP/SP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE△'M37531M4-'	△ * =△\$0000 △.BYTE△'M37531M4-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

★ 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (36P2R for M37531M4-XXXFP, 32P6B for M37531M4-XXXGP, 32P4B for M37531M4-XXXSP) and attach to the mask ROM confirmation form.

\$ 3. Usage conditions Please answer the following ques	stions about usage for us	se in our product inspection:
1) How will you use the XIN-XOUT osc Geramic resonator	illator?	
☐ External clock input	Other ()
At what frequency?	f(XIN) =	MHz

* 4. Comments



GZZ-SH52-90B<85B0>

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4T-XXXGP MITSUBISHI ELECTRIC

Mask ROM number	

	Date:	
seipt	Section head signature	Supervisor signature
Rec		

Note: Please fill in all items marked *.

		Company		TEL		0 U	Submitted by	Supervisor
*	Customer	name		()	Jano		
		Date issued	Date:			lssu sigr		

* 1. Confirmation

Specify the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

			•
Checksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

	27C256		27C512		
EPROM a	ddress		EPROM address		
0000 ₁₆	Area for ASCII codes of the name of the product 'M37531M4T-'		0000 ₁₆	Area for ASCII codes of the name of the product 'M37531M4T-'	
001016			001016		
607F ₁₆			E07F16		
608016	Data		E080 ₁₆	Data DOM (SK 199)	
7FFD ₁₆	ROM (8K-130) bytes		FFFD ₁₆	ROM (8K-130) bytes	
7FFE ₁₆ 7FFF ₁₆			FFFE ₁₆ FFFF ₁₆		

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M4T-' to addresses 000016 to 000F16. ASCII codes 'M37531M4T-' are listed on the right. The addresses and data are in hexadecimal notation.

'M' = 4D16
'3' = 33 16
'7' = 37 16
'5' = 35 16
'3' = 33 16
'1' = 31 16
'M' = 4D16
'4' = 34 ₁₆

Address	
000816	'T' = 54 ₁₆
000916	' – ' = 2D ₁₆
000A 16	FF16
000B ₁₆	FF16
000C ₁₆	FF16
000D ₁₆	FF16
000E 16	FF16
000F 16	FF16

(1/2)



cin	C1 E-	CHIP	Q_RIT	CMOS	MICROC	CIMPL	$IT \vdash P$

GZZ-SH52-90B<85B0>

Mask ROM number	
-----------------	--

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M4T-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531M4T-'	△* =△\$0000 △.BYTE △'M37531M4T-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on the type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

*	2.	Mark	specifi	cation

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531M4T-XXXGP) and attach to the mask ROM confirmation form.

¥ 3. Usage c Please a	onditions answer the following questions	about usage for use in	our product inspection :
(1) How will y	ou use the XIN-XOUT oscillator' Ceramic resonator	?	
	External clock input	☐ Other ()
At what fr	equency?	f(XIN) =	MHz

* 4. Comments



GZZ-SH53-64B<87B0>

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M8-XXXFP/GP/SP MITSUBISHI ELECTRIC

Mask ROM number	

	Date:	
¥	Section head	Supervisor
.idi di	signature	signature
Receipt		
Œ		

Note: Please fill in all items marked ※.

		Company		TEL		υ 0	Submitted by	Supervisor
*	Customer	name		()	atur		
, ,		Date issued	Date:			lssu sign		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce masks based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

☐ M37531M8-XXXFP	☐ M37531M8-XXXGI	P
Checksum code for entire I	EPROM	(hexadecimal notation)

EPROM type (indicate the type used)

Microcomputer name:

	27C256		27C512
EPROM ac	ddress	EPROM a	ddress
000016	Area for ASCII codes of the name of the product 'M37531M8-'	000016	Area for ASCII codes of the name of the product
000F ₁₆	M37531M8-	000F ₁₆	W37531W6-
407F ₁₆		C07F ₁₆	
408016	Data ROM (16K-130)	C080 ₁₆	Data ROM (16K–130)
7FFD16 7FFE16 7FFF16	bytes	FFFD ₁₆ FFFE ₁₆ FFFF ₁₆	bytes

In the address space of the microcomputer, the internal ROM area is from addresses C08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531M8-' to addresses 000016 to 000F16. ASCII codes 'M37531M8-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D ₁₆	0008 16	' – ' = 2D ₁₆
000116	'3' = 33 16	0009 16	FF16
000216	'7' = 37 16	000A 16	FF16
000316	'5' = 35 16	000B 16	FF16
000416	'3' = 33 16	000C 16	FF16
000516	'1' = 31 16	000D 16	FF16
0006 16	'M' = 4D16	000 E ₁₆	FF16
000 716	'8' = 38 16	000F 16	FF16

(1/2)



SINGLE-CHIP 8-BIT	CMOC	MICDOCC	MOUTED
311VGLE-UHIP 8-DIT	CIVIUS	MICHOC	ハハトローヒド

GZZ-SH53-64B<87B0>

|--|

740 FAMILY MASK ROM CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531M8-XXXFP/GP/SP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE△'M37531M8-'	△ * =△\$0000 △.BYTE△'M37531M8-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000F16 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the mask confirmation, the ROM processing is disabled. Write the data correctly.

★ 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (36P2R for M37531M8-XXXFP, 32P6B for M37531M8-XXXGP, 32P4B for M37531M8-XXXSP) and attach to the mask ROM confirmation form.

¾ 3. Usage control Please a Please a ### 3. Usage control ### 4. Usage control	onditions unswer the following questions	about usage for use in	our product inspection:
(1) How will y	ou use the XIN-XOUT oscillator	?	
	Ceramic resonator		
	External clock input	☐ Other ()
At what fre	equency?	f(XIN) =	MHz

* 4. Comments



ROM PROGRAMMING CONFIRMATION FORM

GZZ-SH54-78B<91A0>

ROM number

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4T-XXXGP MITSUBISHI ELECTRIC

	Date:	
	Section head	Supervisor
idi tdi	signature	signature
Receipt		
ш		

Note: Please fill in all items marked ※.

		Company		TEL		υΨ	Submitted by	Supervisor
*	Customer	name		()	uano natur		
,,,		Date issued	Date:			ISSI Sign		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce ROM data based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

Checksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

	27C256			27C512			
EPROM ac	ddress		EPROM ac	ddress			
000016	Area for ASCII codes of the name of the product		000016	Area for ASCII codes of the name of the product			
000F16	'M37531E4T-'		000F ₁₆	'M37531E4T-'			
0010 ₁₆ 607F ₁₆			0010 ₁₆ E07F ₁₆				
608016	Data		E080 ₁₆	Data			
7FFD ₁₆	ROM (8K-130) bytes		FFFD ₁₆	ROM (8K-130) bytes			
7FFE ₁₆ 7FFF ₁₆			FFFE ₁₆ FFFF ₁₆				

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531E4T-' to addresses 000016 to 000F16. ASCII codes 'M37531E4T-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D16	000816	'T'= 5416
000116	'3' = 33 16	0009 16	' – ' = 2D ₁₆
000216	'7' = 37 16	000A 16	FF ₁₆
000316	'5' = 35 16	000B 16	FF 16
000416	'3' = 33 16	000C 16	FF 16
000516	'1' = 31 16	000D 16	FF ₁₆
000616	'E' = 45 ₁₆	000E 16	FF ₁₆
000716	'4' = 34 16	000F 16	FF ₁₆

(1/2)



SINGLE-CHIP	8-RIT	CMOS	MICROC	OMPLITE	=R

GZZ-SH54-78B<91A0>

ROM number	
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740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4T-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531E4T-'	△ * =△\$0000 △.BYTE △'M37531E4T-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the ROM programming confirmation form, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531E4T-XXXGP) and attach to the ROM programming confirmation form.

3. Usage conditions	3
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Please answer the following questions about usage for use in our product inspection:

(1) How will you use the XIN-XOUT oscillator?

Ceramic resonator		
External clock input	☐ Other ()

At what frequency? f(XIN) = MHz

* 4. Comments

(2/2)



GZZ-SH54-79B<91A0>

ROM number

740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4V-XXXGP MITSUBISHI ELECTRIC

	Date:	
	Section head	Supervisor
id	signature	signature
3eceipt		
ш.		

Note: Please fill in all items marked *.

		Company		TEL		υu	Submitted by	Supervisor
*	Customer	name		()	Jano Jatur		
,,,		Date issued	Date:			lssu sigr		

* 1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

Three EPROMs are required for each pattern (Check @ in the appropriate box).

If at least two of the three sets of EPROMs submitted contain identical data, we will produce ROM data based on this data. We shall assume the responsibility for errors only if the mask ROM data on the products we produce differs from this data. Thus, extreme care must be taken to verify the data in the submitted EPROMs.

Checksum code for entire EPROM			(hexadecimal notation)

EPROM type (indicate the type used)

	27C256	T		27C512
EPROM a	ddress	T	EPROM ac	ddress
000016	Area for ASCII codes of the name of the product 'M37531E4V-'		000016	Area for ASCII codes of the name of the product 'M37531E4V-'
000F ₁₆ 0010 ₁₆	WI6766124V		000F16 001016	WIS755124V
607F ₁₆			E07F16	
608016	Data ROM (8K-130)		E080 ₁₆	Data ROM (8K-130)
7FFD16 7FFE16 7FFF16	bytes		FFFD ₁₆ FFFE ₁₆ FFFF ₁₆	bytes

In the address space of the microcomputer, the internal ROM area is from addresses E08016 to FFFD16. The reset vector is stored in addresses FFFC16 and FFFD16.

- (1) Set "FF16" in the shaded area.
- (2) Write the ASCII codes that indicates the name of the product 'M37531E4V-' to addresses 000016 to 000F16. ASCII codes 'M37531E4V-' are listed on the right. The addresses and data are in hexadecimal notation.

Address		Address	
000016	'M' = 4D16	000816	' V ' = 56 16
000116	'3' = 33 16	000916	' – ' = 2D ₁₆
000216	'7' = 37 16	000A 16	FF16
000316	'5' = 35 16	000B 16	FF16
000416	'3' = 33 16	000C 16	FF16
000516	'1' = 31 16	000D 16	FF ₁₆
000616	'E' = 4516	000E 16	FF16
000716	'4' = 34 16	000F 16	FF16

(1/2)



SINGLE-CHIP	8-RIT	CMOS	MICROC	OMPLITE	=R

GZZ-SH54-79B<91A0>

ROM number	
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740 FAMILY ROM PROGRAMMING CONFIRMATION FORM SINGLE-CHIP MICROCOMPUTER M37531E4V-XXXGP MITSUBISHI ELECTRIC

Recommend to writing the following pseudo-command to the assembler source file :

EPROM type	27C256	27C512
The pseudo-command	△ * =△\$8000 △.BYTE △'M37531E4V-'	△ * =△\$0000 △.BYTE △'M37531E4V-'

ASCII codes, that indicates the name of the product, are written in addresses 000016 to 000816 of the EPROM by programming the above pseudo-command, which depends on a type of EPROM to be written, at beginning of the source program.

Note: If the name of the product written to the EPROMs does not match the name of the ROM programming confirmation form, the ROM processing is disabled. Write the data correctly.

* 2. Mark specification

Mark specification must be submitted using the correct form for the package being ordered fill out the appropriate mark specification form (32P6B for M37531E4V-XXXGP) and attach to the ROM programming confirmation form.

)

Ж З. U	sage	conc	litions
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Please answer the following questions about usage for use in our product inspection:

(1) How will you use the XIN-XOUT oscillator?

Ceramic resonator	

	П он <i>(</i>
External clock input	Other (

At what frequency? f(XIN) = MHz

* 4. Comments

(2/2)

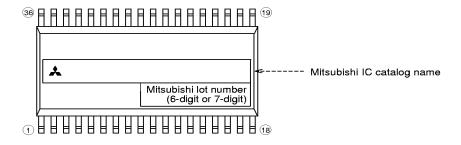


MARK SPECIFICATION FORM 36P2R-A (36-PIN SHRINK SOP) MARK SPECIFICATION FORM

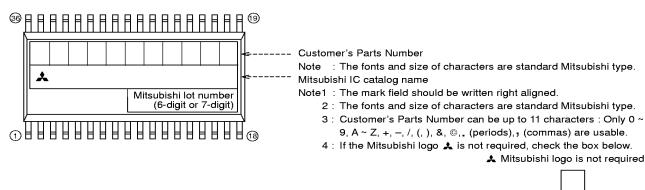
Mitsubishi IC catalog name	
----------------------------	--

Please choose one of the marking types below (A, B, C), and enter the Mitsubishi catalog name and the special mark (if needed).

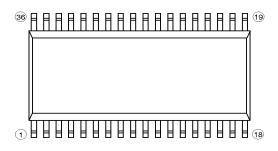
A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi catalog name



C. Special Mark Required



Note1: If the Special Mark is to be Printed, indicate the desired layout of the mark in the left figure. The layout will be duplicated as close as possible.

Mitsubishi lot number (6-digit or 7-digit) and Mask ROM number (3-digit) are always marked.

2: If the customer's trade mark logo must be used in the Special Mark, check the box below.

Please submit a clean original of the logo.

For the new special character fonts a clean font original (ideally logo drawing) must be submitted.

Special logo	required

 The standard Mitsubishi font is used for all characters except for a logo.

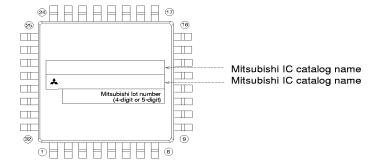


32P6B (32-PIN LQFP) MARK SPECIFICATION FORM

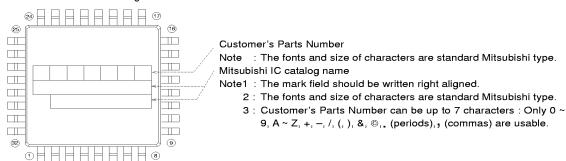
Mitsubishi IC catalog name	
----------------------------	--

Please choose one of the marking types below (A, B), and enter the Mitsubishi catalog name and the special mark (if needed).

A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi catalog name



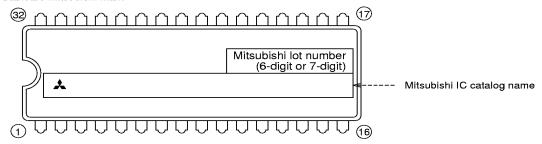


32P4B (32-PIN SHRINK DIP) MARK SPECIFICATION FORM

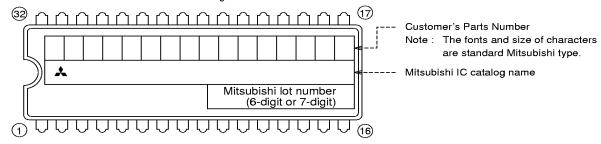
Mitsubishi IC catalog name	
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Please choose one of the marking types below (A, B, C), and enter the Mitsubishi IC catalog name and the special mark (if needed).

A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi catalog name

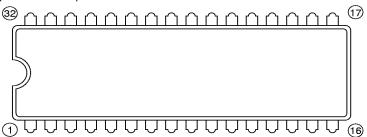


Note1: The mark field should be written right aligned.

- 2: The fonts and size of characters are standard Mitsubishi type.
- 3: Customer's Parts Number can be up to 16 characters: Only 0 ~ 9, A ~ Z, +, -, /, (,), &, ©,. (periods), and, (commas) are usable.
- 4: If the Mitsubishi logo 🛦 is not required, check the box on the right.

▲ Mitsubishi logo is not required

C. Special Mark Required



Note1: If the Special Mark is to be Printed, indicate the desired layout of the mark in the upper figure. The layout will be duplicated as close as possible. Mitsubishi lot number (6-digit or 7-digit) and Mask ROM number (3-digit) are always marked.

- 2 : If the customer's trade mark logo must be used in the Special Mark, check the box on the right. Please submit a clean original of the logo. For the new special character fonts a clean font original (ideally logo drawing) must be submitted.
- 3: The standard Mitsubishi font is used for all characters except for a logo.

Spec	ial lo	ogo	requi	red



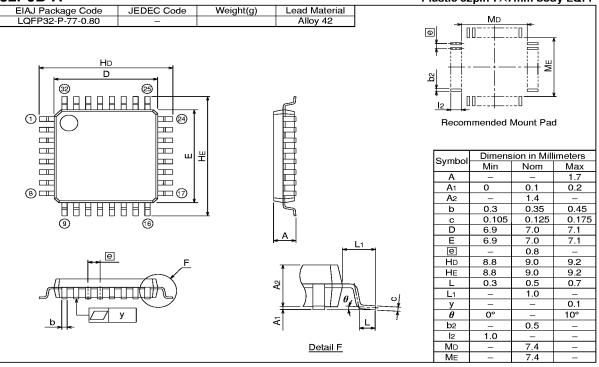


PACKAGE OUTLINE

32P4B Plastic 32pin 400mil SDIP EIAJ Package Code JEDEC Code Weight(g) Lead Material SDIP32-P-400-1.78 Alloy 42/Cu Alloy O e1 D Dimension in Millimeters Symbol Min Nom Max 5.08 0.51 A₁ **A**2 3.8 b 0.35 0.45 0.55 b1 0.9 1.0 1.3 1.03 0.73 0.27 b2 0.63 0.22 0.34 D 27.8 28.0 28.2 е E 8.9 9.05 8.75 SEATING PLANE **e**1 10.16 3.0 $\frac{\mathsf{L}}{\theta}$ 15° 0°

32P6B-A

Plastic 32pin 7×7mm body LQFP

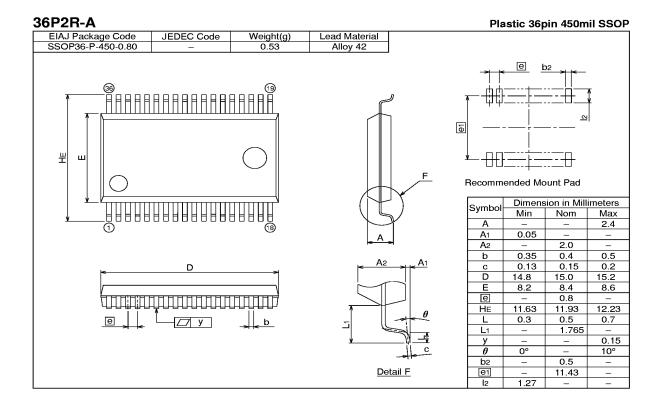




MITSUBISHI MICROCOMPUTERS

7531 Group

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER





MITSUBISHI MICROCOMPUTERS 7531 Group

SINGLE-CHIP 8-BIT CMOS MICROCOMPUTER

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7531 Group DATA SHEET

No.	Revision Description	Rev. date
1.0 First Edi	tion	970822
2.0 Page 1; In Prog In Powe Page 8; The na Fig. 11; Page 11 The se Fig. 12; Fig. 13; Page 15 The ord Fig. 17; Page 21 Explant Fig. 25; Page 23 Explant Fig. 36; Page 32 Explant Fig. 36; Fig. 36; Page 32 Explant Fig. 36; Table 7; Table 8; Table 9; Table 12	FEATURES prammable I/O ports, the pin number of 32-pin version is added. er source voltage, two conditions are added and two are revised. Central Processing Unit (CPU) me of manual, 740 Family Software Manual, is revised. Note is added. ; [Direction registers] PID ntences are revised: Pins set to input are floating, and permit reading pin values. Bit function and the initial value are added. The figure name is revised: port P1P3 control register. ; [Interrupt operation der of No. 3 and 4 is revised. Four bit names are revised: Serial I/O1. ; [Serial I/O1 status register] SIO1STS ations are partly revised. Bit 3 eand 7 explanations of serial I/O1 control register are revised. ; [Serial I/O2 control register] SIO2CON ations are partly revised. Bit 3 explanations are revised. Note is partly revised. ; Reset Circuit ations are partly revised: In the case of f(\(\phi\)) The waveform of clock from built-in ring oscillator is revised. Note 1 is revised. (6) Port P1P3 control register is added. ; A-D Converter ations are partly revised: The WIT instruction is eliminated. ; DATA REQUIRED FOR ROM PROGRAMMING ORDERS ause is added. Characteristics of Vcc is revised. Characteristics of lcc is revised. Characteristics of lcc is revised. 2; Characteristics of lcc is revised. 6 and 47; ROM PROGRAMMING CONFIRMATION FORM are added.	980220

7531 Group DATA SHEET
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